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REPORT OF THE SYNCHROTRON RADIATION VACUUM WORKSHOP*

JULY 25-26, 1983

ROBERT T. AVERY Chairman

June 1984

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F - Post-Workshop Communication from V. Rehn Regarding Carbon Deposition

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PREFACE

The Synchrotron Radiation Vacuum Workshop was held at Lawrence Berkeley Laboratory on July 25-26, 1983. The 41 participants addressed two problems of particular concern to the designers of synchrotron radiation facilities: (a) photoninitiated gas desorption from vacuum chamber walls and (b) carbon deposition on optical components. The purposes of the workshop were twofold: (1) to assess the current state of knowledge on the workshop topics and (2) to suggest near-term R&D on these effects to obtain information upon which to base the final design of the Advanced Light Source storage ring and beam lines.

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1. SUMMARY OF RESULTS

The Synchrotron Radiation Vacuum Workshop was held to consider two vacuum-related problems that bear on the design of storage rings and beam lines for synchrotron radiation facilities. These problems are gas desorption from the vacuum chamber walls and carbon deposition on optical components. Participants surveyed existing knowledge on these topics and recommended studies that should be performed as soon as possible to provide more definitive experimental data on these topics. This data will permit optimization of the final design of the Advanced Light Source (ALS) and its associated beam lines. It also should prove useful for other synchrotron radiation facilities as well.

<u>Gas desorption</u> from practical engineering surfaces bombarded by photons is a complex of multiple processes occuring within the conglomerate surface layers (oxides, carbon, adsorbed gases, etc.). Photoelectrons and secondary electrons play a significant role as they leave the bombarded wall and again as they arrive at a second surface. Photon-initiated desorption dominates over ordinary thermal desorption. (Here, the term "photon-initiated desorption" includes all desorption processes initiated by photons including photon-stimulated desorption, photo desorption and photon-induced dissociation.) Upon startup, the vacuum pressure typically rises from ~10.9 torr by a few orders of magnitude, but continuing photon bombardment gradually reduces the desorption rate as desorbable materials are removed from the wall. Typical experience with electron storage rings is that a vacuum of 10^{-8} torr, which allows a beam lifetime of the order of 10 hours, can be achieved after 1 year of operation. On subsequent pump-downs it takes about one to three months to reach this desirable pressure.

Many photon-initiated desorption experiments have been conducted on carefully prepared scientific samples. Only a few experiments have been done on practical surfaces for vacuum components. To identify the best materials, pretreatments, and configurations for the vacuum chamber, Workshop participants suggested R&D studies that should be performed immediately.

 Test candidate materials for the vacuum chamber interior (e.g., Au, Cu, Ag, Al, Ti, etc.) for their susceptibility to desorption. 2) Test possible surface treatments (e.g., chem-clean, bake, glow discharge, etc.) to judge their effectiveness at removing the desorable materials.

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- Test candidate surface geometries (sawteeth, slopes) and system designs (pumping chambers and strategies, multiple walls) to identify the best combination.
- 4) Perform tests using electron bombardment, but confirm the results using photon bombardment.

For the ALS, a vacuum of 10^{-9} torr will be required to achieve a lifetime of 10 to 12 hours. To minimize the commissioning phase, the system should be able to reach this pressure goal within 1 month of turn-on, and within 1 week on subsequent pump downs. These goals each represent a factor of 10 improvement over typical experience. A proposed design for the ALS Storage Ring vacuum chamber has a large, continuous distributed pump chamber providing evacuation rates of ~1000 liters/second-meter (~10 times greater than that of existing rings). Moreover, most photons strike a water-cooled target in the pump chamber (instead of in the beam chamber as is typical), so less than 10% of the desorbed gas molecules will get into the beam chamber. Favorable comments were voiced for this novel approach, which holds promise for achieving the desired factor of 100 improvement over and above improvements obtained by the suggested R&D program.

<u>Carbon deposition</u> occurs rapidly if the pressure exceeds 10^{-9} torr. It markedly reduces the reflectance of beam line optical components between the carbon K edge (284 eV) and 1 keV. Evidence indicates that the carbon is graphitic and comes from residual gases. The darkening occurs where photons strike the optical surfaces. At temperatures of ~125°C, the deposition rate decreases. At pressures below 10⁻¹⁰ torr, the effect is negligible.

Although an analytical model has been developed for the process, the participants recommended further research to identify the gas species involved (CO, CO₂, hydrocarbons) and to evaluate promising palliative measures, such as heating, having cryosurfaces near the optical components, and removing the coating using O₂ partial pressure. For the short term, the most effective solution is a very high vacuum (< 10^{-9} torr) in the beam lines.

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2. GAS DESORPTION OVERVIEW

Presentations were made by K. Kennedy (LBL), B. Scott (SLAC), J. Schuchman (BNL), A. Mathewson (CERN), D. Lichtman (U. Wisc.), and R. Stulen (Sandia). These were followed by very lively and open discussion. Following are some of the key facts and findings of the Workshop on this topic.

2.1 <u>Typical Electron Ring Experience</u>

The vacuum operating experiences at existing electron storage rings are not identical but there are many similarities. Aluminum chambers seem to behave quite comparably to stainless steel chambers. The following performance is representative of both.

	Beam Current	Approximate Vacuum Pressure (torr)	Approximate Beam Lifetime (hours)
After initial startup:			
1 month	None	10-9	
1 month	Full	10-7	1
1 year	Full	10-8	10
Subsequent pumpdowns:	an a		
1 week	None	10-9	- -
1 week	Full	10-7	[•] 1
3 months	Full	10-8	10

2.2 Gas Desorption Processes

Numerous experiments have been conducted on carefully prepared scientific samples such as crystals cleaved in vacuo and freshly deposited metal surfaces. These are not representative of engineering materials that can be used for construction of a storage ring vacuum system. Such "engineeering" surfaces are

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usually a complex rough conglomerate of oxides, carbon, adsorbed gases and other materials overlaying the metal substrate. These surface constituents have widelyvarying binding energies.

When an engineering surface is bombarded by photons, many desorption processes can occur essentially simultaneously including:

- photon-stimulated desorption
- photo-desorption
- photon-induced dissocation
- thermal desorption
- electron-stimulated desorption

Each is a distinctly different process and can result in desorption of differing gas species. Which process predominates can depend, among other things, on substrate material, surface constituents, bombardment duration and photon energy threshold.

It appears likely that such desorption from engineering surfaces can be attributed primarily to photoelectrons and secondary electrons that were initiated by the photon bombardment. These can cause desorption as they exit through the surface layers of the bombarded wall and again as they re-enter the surface layers at a second surface, which need not be directly illuminated by the primary photon beam. Photons can be scattered to second surfaces but probably are of less significance.

Gas desorption experiments using direct electron bombardment are much easier to perform than ones using photon bombardment. There was concurrence that such direct electron bombardment experiments can produce similar, but not identical, effects and could prove very useful for screening candidates.

2.3 Gas Desorption R&D Studies

Although there is much data in the literature on photon-initiated gas desorption, there is only sparse data relating to engineering surfaces. Here, the term "photon-induced desorption" is used to include all gas-producing processes due to photon bombardment. There was a concensus that further R&D study of gas

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desorption resulting from photon bombardment of engineering surfaces was of high priority and could lead to significantly reduced desorption rates for future storage rings such as the ALS Storage Ring. These R&D studies should include:

- Tests for desorption rates of candidate materials for the vacuum chamber interior including gold, silver, copper, titanium and non-evaporable getter (NEG) materials.
- 2) Tests for change in desorption rates due to candidate pre-treatments and in-situ treatments of vacuum surfaces including chemical-cleaning, vapor cleaning, plating, electropolishing, etching, baking and glow discharge (at elevated temperature).
- 3) Tests of candiate surface geometries (e.g., sawteeth, slopes, roughness) and candidate system arrangements (e.g., pumping, baffles, geometry) to identify the most promising candidates.

The foregoing tests can be conducted using direct electron bombardment to screen candidates, but the results should be confirmed using photon bombardment at a suitable synchrotron radiation beamline. Excessive thermal desorption caused by high bombarding flux densities must be avoided. Surface analysis techniques (e.g., Auger, LEED, SIMS) should be considered to shed further light on the processes. Residual gas analysis (RGA) should be included but special precautions are needed because, for example, the RGA equipment itself can be a source of gases and because many heavier gases may cling to intervening walls before reaching the RGA. Controlled-atmosphere aluminum extrusions (Ref. 83-18, Appendix E) appear very promising.

2.4 ALS Storage Ring Vacuum

A pressure below 10-9 torr is required to achieve a vacuum-related lifetime (1/e) of 12 hours for the electrons in the storage ring. This is approximately a factor 10 more stringent than for typical existing storage rings.

As pointed out earlier, existing storage rings take many months to a year or more to reach their vacuum objective. The ALS staff stated that they hoped to achieve the ALS vacuum in perhaps one-tenth the time. This goal requires a further factor of 10 improvement relative to existing storage ring vacuum systems. The participants concurred with the desirability of this goal.

A proposed design for the ALS Storage Ring vacuum system was presented which has a large continuous distributed pumping chamber connected by a continuous slot to the beam chamber. This arrangement would provide ~ 1000 liter/second-meter of pumping speed from the beam chamber (~10 times that of existing rings). Furthermore, most of the photons would pass through the slot into the pumping chamber where they would strike a water-cooled absorber (except those destined for beam lines). Most of the resulting gas molecules would be directly pumped in the pumping chamber with less than 10% reaching the beam chamber. This would result in a further factor of 10 improvement. Thus, this arrangement holds the promise of achieving the desired factor of 100 improvement relative to existing rings. It also would accommodate use of a range of materials, treatments and pumping techniques in accordance with the outcome of the R&D studies, which could provide even further improvement in the vacuum relative to existing rings. Favorable comments on this concept were voiced by participants. Fabrication considerations for such a large chamber need to be validated. No "fatal flaw" with the concept was suggested.

2.5 Gas Desorption Conclusions

The principal conclusions were:

- 1) Gas desorption due to photon bombardment of engineering surfaces is a complex process for which there is sparse experimental information.
- 2) The concepts for the ALS Storage Ring vacuum system appear promising for achieving the improved vacuum and faster pumpdown desired for the ALS Storage Ring.
- 3) Further R&D studies as presented above should be undertaken with high priority and offer the promise of a significant reduction in desorption rates.

4) A further workshop on this topic may be warranted in approximately 1-2 years if there is sufficient new data to report.

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 \sim 125°C than at room temperature. The authors did not determine which residual gas species (e.g., CO, CO₂, hydrocarbons) were contributing to the process.

The authors formulated an analytical model to represent the observed phenomena. The model looks at the fraction of the surface at steady state that is covered by carbonaceous gas molecules and at their cracking rate which is taken proportional to the fractional coverage. With low fractional coverage, the carbon deposition rate is proportional to pressure which agrees with the observed low deposition rates at low pressures. For a given intensity of photoelectrons, the fractional coverage of adsorbed carbonaceous gas molecules increases as the pressure is increased and when the fractional coverage approaches unity the carbon deposition rate approaches a fixed saturation value in agreement with experimental observations.

A post-workshop communication from V. Rehn (see Appendix F) sheds additional light on the foregoing DESY research. Replotting the equation for the analytical model onto a log-log plot (Appendix F) more clearly shows the saturation values. It shows at pressures below 10^{-9} to 10^{-10} torr that acceptably low carbon deposition rates can be achieved even at very high photon intensities (such as for the Advanced Light Source). Rehn cautions against exposing optical elements to undulator radiation when the ambient pressure is high. He also cautions against relying on the DESY model far outside its region of verification, such as for freeelectron-laser beams.

3.3 Carbon Deposition R&D Studies

Although the German experiments shed considerable light on this topic, the participants recommended that further R&D would be of significant benefit, but not with as high a priority as for the gas desorption R&D studies discussed earlier. These carbon deposition R&D studies should include:

- Tests to evaluate which gas species are significant. (It was noted that CO molecules attach to a surface with the O exposed which suggests that CO may be the principal contributor.
- 2) Tests to assess the benefits of nearby cryogenically-cooled surfaces.

3. CARBON DEPOSITION OVERVIEW

Presentations were made by V. Rehn (China Lake), F. Brown (U. Illinois) and C. Pruett (U. Wisconsin) after which there was open and interactive discussion. Following are some of the key facts and findings of the Workshop on this topic.

3.1 Observed Phenomena

Darkening has occurred on mirrors and other optical surfaces in synchrotron radiation beam lines. Evidence indicates that the darkened surface consists of graphitic carbon overlayers. Reflectance from such optical surfaces is markedly reduced between the carbon K edge (284 eV) and ~1 keV. The darkening occurs primarily where the photon beam strikes and generally increases with photon flux, although on uncoated fused silica mirrors evidence was presented showing reduced darkening at the center of the smile-shaped bombarded area. It was reported that major darkening had occurred within a few months for beam line mirrors operating above 10-7 to 10-8 torr. In contrast, other reports indicated no significant darkening after several years at approximately 10^{-10} torr. The foregoing should not be confused with darkening of insulating materials due to reduction of metal oxides into metal plus oxygen molecules.

3.2 Recent Experiment at DESY

Results of a set of experiments conducted at HASYLAB at DESY, Hamburg, on the deposition of carbon on mirror surfaces were published recently.^[1] This set of experiments has significantly increased the state of knowledge on this topic. It confirms the graphitic carbon nature of the coating. It suggests that photoelectrons cause cracking of carbonaceous gas molecules adsorbed on the mirror surface. They observed for their photon intensities that the darkening rate saturates (no further increase) above pressures in the 10^{-7} torr range. The experiments were mostly conducted in the 10^{-7} to 10^{-8} torr ranges. Lower deposition rates were observed at

 ^[1] Boller, K., Haelbich, R-P, Hogrefe, H., Jark, W., and Kunz, C. "Investigation of Carbon Contamination of Mirror Surfaces Exposed to Synchrotron Radiation," Nucl. Instr. & Meth., <u>208</u>, p. 273 (1983). Also printed as Report DESY SR-82-18.

- 3) Tests of the effectiveness of a partial pressure of O_2 (or other oxidant) in removing accumulated carbon, perhaps in conjunction with heating, photon bombardment, or glow discharge.
- 4) Tests of the effect of temperatures above 125°C.

It again was the concensus that electrons could be used to simulate the process, but the results should be confirmed using photons. Saturation effects need to be considered when designing the tests.

3.4 Carbon Deposition Conclusions

The principal conclusions were:

- 1) Use of vacuum below 10-9 to 10-10 torr, perhaps in conjunction with moderate heating, is a short-term solution.
- 2) The R&D studies suggested above should be performed.
- 3) A further workshop on this topic is warranted only if there is new evidence to present.

APPENDIX A

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Agenda

SYNCHROTRON RADIATION VACUUM WORKSHOP

Lawrence Berkeley Laboratory Building 71 Conference Room July 25-26, 1983

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MONDAY, July 25, 1983

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8:30 am	Registration, Bldg. 71 Conference Room	
9:00 am	Welcome	K.H. Berkner
9:10 am	Introduction to Workshop	R. Avery
9:20 am	The Advanced Light Source Project	R. Sah
9:40 am	The ALS Vacuum System and Related R&D Program	K. Kennedy
10:00 am	Gas Desorption Experience at Electron Storage Rings	B. Scott, J. Schuchman
10:20 am	Gas Desorption Experiment at Orsay	A. Mathewson
11:20 am	Physics of Gas Desorption	D. Lichtman, R. Stulen
12:45 pm	Lunch	
1:30 pm	Guided Discussion on Gas Desorption Including Possible Future Progress	E. Garwin
3:30 pm	Intermission	
3:45 pm	Guided Discussion (continued)	E. Garwin
4:45 pm	Final Conclusions and Recommendations on Gas Desorption	E. Garwin
5:30 pm	Social Hour	
6:30 pm	Dinner	

Agenda (continued) SYNCHROTRON RADIATION VACUUM WORKSHOP

July 25-26, 1983

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TUESDAY, July 26, 1983

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8:30 am	Announcements and Introduction	R. Avery
8:45 am	Experiences with Darkening of Optical Components by Photons	V. Rehn, F. Brown and
		C. Pruett
10:00 am	Intermission	
10:20 am	Physics of Darkening of Optical Components	D. Lichtman
	by Photons and Photoelectrons	
11:45 am	Discussion on Darkening of Optical Components	V. Rehn
•	Including Possible Alleviation and Future Programs	4
12:45 pm	Lunch	
1:45 pm	Final Conclusions and Recommendations	V. Rehn
2:30 pm	Conclusion of Workshop	

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APPENDIX B

DISUCSSION GUIDELINES

SYNCHROTRON RADIATION VACUUM WORKSHOP

GAS DESORPTION TOPICS

- Storage Ring Experience
 - Without electron beam
 - With electron beam versus time
 - Ditto after venting for new component
 - Gases desorbed: H₂, CO, CO₂, CH₄, etc.

• Experimental Evidence

- Neutrals versus ions
- Threshold energy
- Incident angl.

Physics Processes Involved

- Photon-stimulated desorption (PSD)
- Photo-desorption
- Role of photo-electrons and secondary electrons
- Effect of electrical or magnetic fields
- Gas Species
 - Where does H_2 , CO, CO₂ and CH₄ come from?
- <u>Materials</u>
 - Al, SS, Cu, Au, Ti, AlZr.
 - Electro-plated thickness?
 - Role of surface oxides, carbon, etc.

GAS DESORPTION TOPICS (continued)

- Surface Treatment
 - Acid or alkali clean
 - Electropolish
 - Nitride
 - Electron bombard
 - Glow discharge
 - Bake
- Future Experiments?
 - Simulate by electron-stimulated desorption (ESD)
 - Simulate by ion-stimulated desorption (ISD)
 - Verify using photons? Measure neutrals or ions? At what facility? Collaborative effort?
 - Surface analysis (Auger, ESCA/XPS)?
- <u>Comments on ALS Vacuum Concepts</u>
- Promising Approaches to Pursue
 - Materials?
 - Treatments?
 - Other?

• <u>Need for Future Workshop?</u>

CARBON DEPOSITION TOPICS

- Observed Darkening versus:
 - Pressure
 - Residual gas constitutents
 - Time
 - Photon energy (wavelength)
 - Angle of incidence
 - Photon intensity
- Source of Contamination:
 - On surface when installed?
 - Residual gas? Which species?
- Experimental evidence
 - Nature of coating? Graphitic?
- Processes Involved
 - Reduction of CO, CO₂, CH₄, etc.?
 - Role of photons, photoelectrons and secondary electrons?
- Possible Prevention or Cleaning
 - More pumping (e.g., cryo-pumping)?
 - Heating or cooling?
 - Partial pressure of O₂, NO or H₂ possibly at elevated temperature?
 - Glow discharge?

• Future Experiments?

- On any of above "cures"?
- Can photon process be simulated by electron or ion bombardment?
- Surface analysis?
- Any others?
- Need for Future Workshop?

APPENDIX C

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APPENDIX D

ELECTRON STORAGE RING/VACUUM DATA SHEETS FROM RESPONDING FACILITIES

	<u>Page</u>
China	· · ·
Beijing Electron Positron Collider (BEPC), IHEP, Beijing	D-2
Hefei Synchrotron Radiation Laboratory (HESYRL), Hefei	D-4
Germany	
BESSY, Berlin	D-6
Italy	
ADONE, Frascati	D-8
Japan	
Photon Factory, NLHEP, Tsukuba	D-10
SOR, ISSP, Univ. of Tokyo	D-12
Tristan Accumulation Ring, KEK, Tsukuba	D-14
Tristan Main Ring, KEK, Tsukuba	D-15
UVSOR, Inst. for Molecular Science, Okasaki	D-16
TERAS, Electrotechnical Laboratory, Ibaraki	D-18
Switzerland	
LEP, CERN	D-20
<u>U.K.</u>	
Synchrotron Radiation Source (SRS), Daresbury	D-22
U.S.A.	
SURF, NBS, Gaithersburg, MD	D-25
SPEAR, SLAC, Stanford, CA	D-27
PEP, SLAC, Stanford, CA	D-29
SLC Damping Ring, SLAC, Stanford, CA	D-31
VUV Ring, NSLS, BNL, Upton, NY	D-33
X-Ray Ring, NSLS, BNL, Upton, NY	D-35
Advanced Light Source, LBL, Berkeley, CA	D-37

ELECTRON STORAGE RING/VACUUM DATA SHEET
Beijing Electron Positron
Institution Institute of High Energy Physics Data Supplied by Zhang Nai-Sen
Date of first circulating beam (or goal) 1988
Beam energy, Typical (Eo. GeV)
Max. (Em, Gev) 2.8
Avg. Beam current, Typical(I ₀ , mA) <u>200</u>
Max. (1 _m , mA) 200 Radius of curvature in bend magnets (m)
Ring circumference (m)
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) or acceleration voltage/turn due to bend magnets at $E_0(kV)$
VACUUM CHAMBER:
Aperture: horizontal (cm) 12 vertical(cm) 5.8
Chamber material <u>Al Allay</u>
absorber) if different from chamber material
Chamber preparation before installation Perchlorethylene vapor degreasing-
alkaline detergent - demineralized water
In-situ chamber treatment (e.g. bake, glow): <u>glow-discharge</u>
VACUUM PUMPING:
<u>VACUUM PUMPING</u> : Distributed pumping: type <u>Ti</u> Distributed Sputter-Ion Pump total speed <u>46 up 1/4</u>
VACUUM PUMPING: Distributed pumping: type <u>Ti</u> Distributed Sputter-Ion Pump total speed <u>4600 1/s</u>
<u>VACUUM PUMPING:</u> Distributed pumping: type <u>Ti</u> <u>Distributed Sputter-Ion Pump</u> total speed <u>46 vo 1/s</u> Lumped pumping: type <u>IP</u> <u>40 × 500 ²/s</u> <u>32 × 50 ²/s</u> total speed <u>216 ao ²/s</u>
VACUUM PUMPING:Distributed pumping: typeTiDistributed Sputter - Ion Pumptotal speed4600 l/sLumped pumping: typeIP40 x 500 l/stotal speed21600 l/sDistance between lumped pumps (m)Avg.7
VACUUM PUMPING:Distributed pumping: type T_i Distributed Sputter - Ion Pumptotal speed $46 vo l/s$ Lumped pumping: type IP $4v \times 5vo l/s$ total speed $216 co l/s$ Distance between lumped pumps (m) $Avg. \sim 7$
VACUUM PUMPING:Distributed pumping: typeTiDistributed Sputter - Ion Pump 4600 1/sLumped pumping: typeIP40 x 500 1/sLumped pumping: typeIP40 x 500 1/s21600216001/sDistance between lumped pumps (m)Avg.7How is vacuum pressure monitored?operating prassure $\leq 1.5^{\circ} \times 10^{-8}$ Torr
VACUUM PUMPING:Distributed pumping: typeTiDistributed Sputler - Ion Pump 46 vo 1/sLumped pumping: typeIP40 x 500 %32 × 50 %Lumped pumping: typeIP40 x 500 %32 × 50 %Distance between lumped pumps (m)Avg. $\sqrt{7}$ How is vacuum pressure monitored?Operating prassure $\leq 1.5^{\circ} \times 10^{-8}$ Torr (Design value)Ion gages
VACUUM PUMPING:Distributed pumping: typeTiDistributed Sputter - Ion Pump 46 vo 1/sLumped pumping: typeIP40 x 500 %32 x 50 %Lumped pumping: typeIP40 x 500 %12 x 50 %Distance between lumped pumps (m)Avg.MAvg.M1How is vacuum pressure monitored?Operating prassure < 1.5 x 100 % Torr (Design value)Procedures to avoid ion-trapping?
VACUUM PUMPING: Distributed pumping: type Ti Distributed Sputter - Ion Pump total speed 4600 [/s] Lumped pumping: type TP 40 x 500 % 32 x 50 % total speed 21600 % 32 x 50 % 100 % Distance between lumped pumps (m) Avg. N 7 How is vacuum pressure monitored? operating prassure ≤ 1.5 × 10 ⁻⁸ Torr $(Design value)$ Ion gages Procedures to avoid ion-trapping?
VACUUM PUMPING:Distributed pumping: type T_i Distributed Sputler - Ion Pump 46 vo 1/sLumped pumping: type IP $4v \times 5v \cdot \frac{1}{s}$ $32 \times 5 \cdot \frac{2}{s}$ Lumped pumping: type IP $4v \times 5v \cdot \frac{1}{s}$ $32 \times 5 \cdot \frac{2}{s}$ Distance between lumped pumps (m) $Avg.$ $Ng.$ N How is vacuum pressure monitored? $operating prassure \leq 1.5 \times 10^{-8}$ $Torr$ $(Design value)$ Ion gagesProcedures to avoid ion-trapping?Published articles describing the machine and/or vacuum systemSummaryof the PreliminaryDesign of Beiging $2\cdot \frac{2}{2}$ Sum Electron
VACUUM PUMPING: Distributed pumping: type Ti Distributed Sputler - Ion Pump total speed Lumped pumping: type IP 40 × 500 %/s 32 × 50 %/s Lumped pumping: type IP 40 × 500 %/s 32 × 50 %/s Distance between lumped pumps (m) Avg. N 7 How is vacuum pressure monitored? Operating prassure ≤ 1.5 × 10 ⁻⁸ Torr (Design value) Ion gages Procedures to avoid ion-trapping? Published articles describing the machine and/or vacuum system Summary of the Preliminary Design of Beizing 2.2/2.8 Gev Position Collider
VACUUM PUMPING: Distributed pumping: type <u>Ti</u> Distributed Sputler-Ion Pump total speed <u>4600 1/s</u> Lumped pumping: type <u>IP</u> 40 × 500 % <u>7</u> total speed <u>21600 R/s</u> Distance between lumped pumps (m) <u>Avg. ~ 7</u> How is vacuum pressure monitored? <u>operating prassure ≤ 1.5 × 10⁻⁸ Torr</u> (Design value) Ion gages Procedures to avoid ion-trapping? Published articles describing the machine and/or vacuum system <u>Summary of the Preliminary Design of Beijing 2.2/2.9 Geex Electron</u> <u>Position Collider</u> <u>Justitute of High Energy Physics Acedemia Simica</u> <u>Dec. 198 2</u>
VACUUM PUMPING: Distributed pumping: type <u>Ti</u> Distributed Sputler-Ion Pump total speed <u>4600 1/3</u> Lumped pumping: type <u>IP</u> 40×500 f/s <u>32×50 g/s</u> total speed <u>21600 g/s</u> Distance between lumped pumps (m) <u>Avg. ~ 7</u> How is vacuum pressure monitored? <u>operating prassure ≤ 1.5 × 10⁻⁸ Torr</u> (Design value) Ion gages Procedures to avoid ion-trapping? Published articles describing the machine and/or vacuum system <u>Summary of the Preliminary Design of Beijing 2.2/2.9 Gev Electron</u> <i>Pasifin Collider</i> <u>Institute g High Energy Physics Acedemia Simica</u> <u>Dec. 1982</u> Additional features or comments
VACUUM PUMPING: Distributed pumping: type
VACUUM PUMPING: Distributed pumping: type

ELECTRON STORAGE RING/VACUUM DATA SHEET

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Des	at Beam Energy (GeV)		2.8 42			<u></u>
5	and Beam Current (mA)		130 m	£.		
Pre	ssure required to achieve of	desired li	ifetime (Torr		1.5 × 10-8	
OPE	RATING EXPERIENCE		·	· · · · · · · · · · · · · · · · · · ·	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	
		Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr)	Beam Lifetime (Hours)
1.	After first week of beam					
2.	After 2 months of beam					
3.	After 1 year of beam			<u>.</u>		
4.	Now					
Com	ments					
Com Aft	now ments er opening chamber to inst	all a new	ring vacuum	component:		
Com Aft	ments er opening chamber to inst After one week	all a new	ring vacuum	component:		
Com Aft 1. 2.	ments er opening chamber to inst After one week After one month	all a new	ring vacuum	component:		
Com Aft 1. 2. 3.	now ments er opening chamber to inst After one week After one month After 6 months	all a new	ring vacuum	component:		
Com Aft 1. 2. 3.	now ments er opening chamber to inst After one week After one month After 6 months t procedure is followed wh	all a new	ring vacuum	component:		
Com Aft 1. 2. 3. Wha	ments er opening chamber to inst After one week After one month After 6 months It procedure is followed wh ments	all a new	ring vacuum	component:		
Com Aft 1. 2. 3. Wha	now ments er opening chamber to inst After one week After one month After 6 months t procedure is followed wh ments	all a new	ring vacuum	component:		

*Fraction of beam remaining is _____

ELECTRON STORAGE RING/VACUUM DATA SHEET

Institution <u>HESTRI</u> Data supplied by <u>Bao Zhong-mou</u> Date of first circulating beam (or goal) <u>1987</u> Beam energy; Typical (E ₀ , GeV) Max. (E _m , Gev) Max. (E _m , Gev) Max. (E _m , MA) <u>300</u> Max. (E _m , Gev) Arg. (Each end magnets (m) <u>2.22</u> Synchrotron radiation power due to bend magnets at E ₀ , I ₀ (kW) <u>4.89</u> or acceleration voltage/turn due to bend magnets at E ₀ , I ₀ (kW) <u>4.89</u> or acceleration voltage/turn due to bend magnets at E ₀ (kV) <u>16.31</u> VACUUM CHAMBER: Aperture: horizontal (cm) <u>4.0</u> vertical(cm) ⁺ -2.1 Chamber material <u>statulaes stael</u> Material impinged by Synchrotron radiation from the bend magnets (photon absorber) if different from chamber material <u>Cu</u> Chamber preparation before installation <u>parchlorethylene vspor,degreasing</u> alkaline,detergent-demineralized vater In-situ chamber treatment (e.g. bake, glow): <u>glov-discharge and bake</u> VACUUM PUMPING: Distributed pumping: type <u>24001/s</u> Lumped pumping: type <u>sputter ion</u> total speed <u>9200 1/s</u> Distance between lumped pumps (m) <u>3.0</u> How is vacuum pressure monitored? <u>Ion gauge or Ion current of SIP</u> Procedures to avoid ion-trapping? <u>none</u> Published articles describing the machine and/or vacuum system <u>"Hefei Synchrotron</u> <u>Radiation Laboratory(HESYRL) An 800 Mev Electron Storage Ring and Its</u> Synchrotron Radiation Experiment Area", Synchrotron Radiation Instry- mentation Conference.9-13 August 1982, Hanburg-DESY	Name of the Ring HASYRT.	Date July 18
Beam energy; Typical (E ₀ , GeV) <u>0.800</u> Max. (E _m , GeV) <u>0.800</u> Max. (I _m , mA) <u>300</u> Max. (I _m , mA) <u>300</u> Radius of curvature in bend magnets (m) <u>2.22</u> Ring circumference (m) <u>66.13</u> Synchrotron radiation power due to bend magnets at E ₀ , I ₀ (kW) <u>4.89</u> or acceleration voltage/turn due to bend magnets at E ₀ (kV) <u>16.31</u> <u>VACUUM CHAMBER</u> : Aperture: horizontal (cm) <u>4.0</u> vertical(cm) ⁴ - <u>2.1</u> Chamber material <u>Stainlass steel</u> Material impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber material <u>Ga</u> Chamber preparation before installation <u>perchlorethylene vepor,degreasing</u> alkaline,detergent-demineralized vater <u>1n-situ chamber treatment (e.g. bake, glow): glow-discharge and bake</u> <u>VACUUM PUMPING</u> : Distributed pumping: type <u>sputter Ion</u> total speed <u>24001/s</u> Distance between lumped pumps (m) <u>3.0</u> How is vacuum pressure monitored? <u>Ion gauge or Ion current of SIP</u> Procedures to avoid ion-trapping? <u>none</u> Published articles describing the machine and/or vacuum system <u>"Hefei Synchrotron</u> <u>Radiation Laboratory(HESYRL) An 800 Mev Electron Storage Ring and Its</u> Synchrotron Radiation Experiment Area", Synchrotron Radiation Instru- <u>mentation Conference.9-13 Accust 1982, Hanburg-DESY</u>	Institution <u>HESYRI</u> Date of first circulating beam (or goal) <u>198</u>	Data supplied by <u>Bao Zhong-mou</u> 37
Avg. Beam current, Typical(10, mA) 300 Max. (1m, mA) Max. (1m, mA) Radius of curvature in bend magnets (m) 2,22 Ring circumference (m)66.13 Synchrotron radiation power due to bend magnets at E0, I0 (kW) 4.89 or acceleration voltage/turn due to bend magnets at E0(kV)16.31 VACUUM CHAMBER: Aperture: horizontal (cm) +4.0 vertical(cm) +2.1 Chamber material gtainless steel Material impinged by Synchrotron radiation from the bend magnets (photon absorber) if different from chamber material Gu Chamber preparation before installation parchlorethylene vapor, degreasing- alkalino, detergent-demineralized vater In-situ chamber treatment (e.g. bake, glow): glov-discharge and bake VACUUM PUMPING: Distributed pumping: type total speed 22001/s Distance between lumped pumps (m) 3.0 How is vacuum pressure monitored? Ion gauge or Ion current of SIP Procedures to avoid ion-trapping? none Published articles describing the machine and/or vacuum system "Hefei Synchrotron radiation Instru- mentation Conference, 9-13 August 1982, Hanburg-DESY	Beam energy, Typical (E ₀ , GeV) <u>0.800</u> Max. (E _m , Gev)	
Radius of curvature in bend magnets (m) 2.22 Ring circumference (m)66.13 Synchrotron radiation power due to bend magnets at E ₀ , I ₀ (kW) 4.89 or acceleration voltage/turn due to bend magnets at E ₀ (kV)16.31 VACUUM CHAMBER: Aperture: horizontal (cm) 4.0 vertical(cm) ⁺ -2.1 Chamber material Stainless steel Material impinged by Synchrotron radiation from the bend magnets (photon absorber) if different from chamber material Cu Chamber preparation before installation perchlorethylene vspor, degreasing— alkaline, detergent-demineralized vater In-situ chamber treatment (e.g. bake, glow): glov-discharge and bake VACUUM PUMPING: Distributed pumping: type sputter Ion total speed 24001/s Lumped pumping: type sputter Ion total speed 9200 1/s Distance between lumped pumps (m) 3.0 How is vacuum pressure monitored? Ion gauge or Ion current of SIP Procedures to avoid ion-trapping? none Published articles describing the machine and/or vacuum system "Hefei Synchrotron Radiation Laboratory(HESYRL) An 800 Mev Electron Storage Ring and Its Synchrotron Radiation Experiment Area", Synchrotron Radiation Instru- mentation Conference, 9-13 August 1982, Hanburg-DESY	Avg. Beam current, Typical(Io, mA) 300	
Synchrotron radiation power due to bend magnets at E ₀ , I ₀ (kW) <u>4.89</u> or acceleration voltage/turn due to bend magnets at E ₀ (kV) <u>16.31</u> <u>VACUUM CHAMBER:</u> Aperture: horizontal (cm) <u>4.0</u> vertical(cm) ⁺ -2.1 Chamber material <u>Stainless steel</u> Material impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber material <u>Cu</u> Chamber preparation before installation <u>perchlorethylene vapor,degreasing</u> <u>alkaline,detergent-demineralized vater</u> In-situ chamber treatment (e.g. bake, glow): <u>glow-discharge and bake</u> <u>VACUUM PUMPING:</u> Distributed pumping: type <u>Sputter ion</u> total speed <u>24001/5</u> Lumped pumping: type <u>9200 1/5</u> Distance between lumped pumps (m) <u>3.0</u> How is vacuum pressure monitored? <u>Ion gauge or Ion current of SIP</u> Procedures to avoid ion-trapping? <u>none</u> Published articles describing the machine and/or vacuum system <u>"Hefei Synchrot</u> ron <u>Radiation Leboratory(HESTRL) An 800 Mev Electron Storage Ring and Its</u> Synchrotron Radiation Synchrotron Radiation Instru- <u>mentation Conference, 9-13 August 1982, Hanburg-DESY</u>	Radius of curvature in bend magnets (m) 2.2 Ring circumference (m)66.13	22
VACUUM CHAMBER: Aperture: horizontal (cm)	Synchrotron radiation power due to bend mag or acceleration voltage/turn due to bend m	nets at E_0 , I_0 (kW) <u>4.89</u> nagnets at E_0 (kV) <u>16.31</u>
Aperture: horizontal (cm)	VACUUM CHAMBER:	•
absorber) if different from chamber material <u>Cu</u> Chamber preparation before installation <u>perchlorethylene vspor,degreasing</u> alkaline,detergent-demineralized vater In-situ chamber treatment (e.g. bake, glow): <u>glov-discharge and bake</u> VACUUM PUMPING: Distributed pumping: type <u>sputter ion</u> total speed <u>24001/s</u> Lumped pumping: type <u>sputter Ion</u> total speed <u>9200 1/s</u> Distance between lumped pumps (m) <u>3.0</u> How is vacuum pressure monitored? <u>Ion gauge or Ion current of SIP</u> Procedures to avoid ion-trapping? <u>none</u> Published articles describing the machine and/or vacuum system <u>"Hefei Synchrot</u> ron <u>Radiation Læboratory(HESYRL) An 800 Mev Electron Storage Ring and Its</u> <u>Synchrotron Radiation Experiment Area".Synchrotron Radiation Instru-</u> mentation Conference.9-13 August 1982.Hanburg-DESY	Aperture: horizontal (cm) <u>+-4.0</u> Chamber material <u>Stainless Steel</u> Material impinged by synchrotron radiation	_ vertical(cm) ⁺ -2.1 from the bend magnets (photon
Chamber preparation before installation perchlorethylene vapor,degreasing- mikaline,detergent-demineralized vater In-situ chamber treatment (e.g. bake, glow): glow-discharge and bake VACUUM PUMPING: Distributed pumping: type	absorber) if different from chamber materia) <u>Cu</u>
In-situ chamber treatment (e.g. bake, glow): glow-discharge and bake VACUUM PUMPING: Distributed pumping: type sputter ion total speed 24001/s Lumped pumping: type sputter Ion total speed 9200 1/s Distance between lumped pumps (m) 3.0 How is vacuum pressure monitored? Ion gauge or Ion current of SIP Procedures to avoid ion-trapping? none Published articles describing the machine and/or vacuum system "Hefei Synchrotron Radiation Imboratory(HESYRL) An 800 Mev Electron Storage Ring and Its Synchrotron Radiation Experiment Area".Synchrotron Radiation Instrumentation Conference.9-13 August 1982, Hanburg-DESY	Chamber preparation before installation per alkaline.detergent-demineralized va	chlorethylene vapor, degreasing
In-situ chamber treatment (e.g. bake, glow): glow-discharge and bake VACUUM PUMPING: Distributed pumping: type sputter ion total speed 24001/s Lumped pumping: type sputter Ion total speed total speed 9200 1/s Distance between lumped pumps (m) 3.0 How is vacuum pressure monitored? Ion gauge or Ion current of SIP Procedures to avoid ion-trapping? none Procedures to avoid ion-trapping? none Published articles describing the machine and/or vacuum system "Hefei Synchrotron Radiation Experiment Area", Synchrotron Radiation Instru- mentation Conference.9-13 August 1982, Hanburg-DESY	,	
In-situ chamber treatment (e.g. bake, glow): glow-discharge and bake VACUUM PUMPING: Distributed pumping: type sputter ion total speed 24001/s Lumped pumping: type sputter Ion g200 1/s Distributed pumping: type monitored? Ion gauge or Ion current of SIP Procedures to avoid ion-trapping? none none Published articles describing the machine and/or vacuum system "Hefei Synchrotron Radiation Imboratory(HESYRL) An 800 Mev Electron Storage Ring and Its Synchrotron Radiation Experiment Area", Synchrotron Radiation Instru- mentation Conference.9-13 August 1982, Hanburg-DESY	***************************************	
VACUUM PUMPING: Distributed pumping: type sputter ion total speed 24001/s Lumped pumping: type sputter Ion total speed 9200 1/s Distance between lumped pumps (m) 3.0 How is vacuum pressure monitored? Ion gauge or Ion current of SIP Procedures to avoid ion-trapping? none Procedures to avoid ion-trapping? none Published articles describing the machine and/or vacuum system "Hefei Synchrotron Radiation Importance". Published articles describing the machine and/or vacuum system "Hefei Synchrotron readiation Importance". Published articles describing the machine and/or vacuum system "Hefei Synchrotron readiation Importance". Published articles describing the machine and/or vacuum system "Hefei Synchrotron readiation Importance". Published articles describing the machine and/or vacuum system "Hefei Synchrotron readiation Importance". Published articles describing the machine and/or vacuum system "Hefei Synchrotron readiation Instru- Bentation Conference.9-13 August 1982.Hanburg-DESY	In-situ chamber treatment (e.g. bake, glow)	glov-discharge and bake
Distributed pumping: type <u>sputter ion</u> total speed <u>24001/s</u> Lumped pumping: type <u>sputter Ion</u> total speed <u>9200 1/s</u> Distance between lumped pumps (m) <u>3.0</u> How is vacuum pressure monitored? <u>Ion gauge or Ion current of SIP</u> Procedures to avoid ion-trapping? <u>none</u> Published articles describing the machine and/or vacuum system <u>"Hefei Synchrotron</u> Radiation Laboratory(HESYRL) An 800 Mev Electron Storage Ring and Its Synchrotron Radiation Experiment Area".Synchrotron Radiation Instru- mentation Conference.9-13 August 1982.Hanburg-DESY	VACUUM PUMPING:	
Lumped pumping: type sputter Ion total speed 9200 1/8 Distance between lumped pumps (m) 3.0 How is vacuum pressure monitored? Ion gauge or Ion current of SIP Procedures to avoid ion-trapping? none Published articles describing the machine and/or vacuum system "Hefei Synchrotron Radiation Laboratory(HESYRL) An 800 Mev Electron Storage Ring and Its Synchrotron Radiation Experiment Area", Synchrotron Radiation Instru- mentation Conference.9-13 August 1982, Hanburg-DESY	Distributed pumping: type total speed 24001/s	sputter jon
Distance between lumped pumps (m) <u>3.0</u> How is vacuum pressure monitored? <u>Ion gauge or Ion current of SIP</u> Procedures to avoid ion-trapping? <u>none</u> Published articles describing the machine and/or vacuum system <u>"Hefei Synchrotron</u> <u>Radiation Leboratory(HESYRL) An 800 Mev Electron Storage Ring and Its</u> <u>Synchrotron Radiation Experiment Area</u> ".Synchrotron Radiation Instru- <u>mentation Conference.9-13 August 1982, Hanburg-DESY</u>	Lumped pumping: type sputter Ion total speed 9200 1/s	
How is vacuum pressure monitored? <u>Ion gauge or Ion current of SIP</u> Procedures to avoid ion-trapping? <u>none</u> Published articles describing the machine and/or vacuum system <u>"Hefei Synchrotron</u> <u>Radiation Leboratory(HESYRL) An 800 Mev Electron Storage Ring and Its</u> <u>Synchrotron Radiation Experiment Area</u> ".Synchrotron Radiation Instru- <u>mentation Conference.9-13 August 1982.Hanburg-DESY</u>	Distance between lumped pumps (m) 3.0	
Procedures to avoid ion-trapping? <u>none</u> Published articles describing the machine and/or vacuum system <u>"Hefei Synchrotron</u> <u>Radiation Leboratory(HESYRL) An 800 Mev Electron Storage Ring and Its</u> <u>Synchrotron Radiation Experiment Area</u> <u>Synchrotron Radiation Instru-</u> <u>mentation Conference.9-13 August 1982.Hanburg-DESY</u>	How is vacuum pressure monitored? Ion gau	ge or Ion current of SIP
Published articles describing the machine and/or vacuum system <u>"Hefei Synchrotron</u> <u>Radiation Leboratory(HESYRL) An 800 Mev Electron Storage Ring and Its</u> <u>Synchrotron Radiation Experiment Area</u> ".Synchrotron Radiation Instru- mentation Conference.9-13 August 1982.Hanburg-DESY	Procedures to avoid ion-trapping? <u>none</u>	
<u>Radiation Leboratory(HESIRL) An 800 Mev Electron Storage Ring and Its</u> <u>Synchrotron Radiation Experiment Area",Synchrotron Radiation Instru-</u> <u>mentation Conference,9-13 August 1982,Hanburg-DESY</u>	Published articles describing the machine and	nd/or vacuum system <u>"Hefei Synchrotron</u>
Synchrotron Radiation Experiment Area", Synchrotron Radiation Instru- mentation Conference.9-13 August 1982. Hanburg-DESY	Radiation Laboratory (HESIRL) An 800	Mev Electron Storage Ring and Its
Bentation Conierence.9-12 August 1982.Hanburg-DESY	Synchrotron Radiation Experiment Are	a".Synchrotron Radiation Instru-
μ_{α}	Additional features or comments No-	2. Han burg-DESI
	AUGICIONAL LEAGULES OF CUMMERTS NOTE	

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HESYRL , page 2

ELECTRON STORAGE RING/VACUUM DATA SHEET

DESIRED VACUUM:

Desired beam lifetime (hours)	10.0		
at Beam Energy (GeV)	0.800		
and Beam Current (mA)	300		
Fraction of beam remaining			
Pressure required to achieve	desired lifetime	(Torr) 10-9	

OPERATING EXPERIENCE

		Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr)	Beam Lifetime* (Hours)
1.	After first week of beam	×		-		
2.	After 2 months of beam		-		· · · · · · · · · · · · · · · · · · ·	
3.	After 1 year of beam			-		
4.	Now					·~.

Comments _____

After opening chamber to install a new ring vacuum component:

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1.	After one week	-		
2.	After one month			
3.	After 6 months			

What procedure is followed when chamber is opened

Comments _____

*Fraction of beam remaining is _____

ELECTRON STORAGE RING/VACUUM DATA SHEET

Name of the Ping BESSY Date 09.08-1983
Institution DESCY CODUL Data Supplied by G Milhaunt
Date of first circulating beam (or goal) Dezember 1981
Beam energy, Typical (E ₀ , GeV) 0.775
Max. (Em, Gev) 0.800
Avg. Beam current, $ yp cal(I_0, mA) = 200$
Radius of curvature in bend magnets (m) 1 78
Ring circumference (m) 62.4
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) 3.5 or acceleration voltage/turn due to bend magnets at $E_0(kV)$ 18
VACUUM_CHAMBER:
Aperture: horizontal (cm) ± 3.0 vertical(cm) ± 2.0
Chamber material Stainless Steel
absorber) if different from chamber material <u>Cu</u>
Chamber preparation before installation Per chlorettylene vapor degreasing-
ultrasound cleaning - heating to $\tau \ge 200$ C ^e
In-situ chamber treatment (e.g. bake. glow): bake τ ≥ 150° C [●]
VACUUM PUMPING:
VACUUM PUMPING: Distributed pumping: type Sputter Top
VACUUM PUMPING: Distributed pumping: type <u>Sputter Ion</u> total speed ~ 1200 1/c
VACUUM PUMPING: Distributed pumping: type <u>Sputter Ion</u> total speed <u>~ 1200 l/s</u> Lumped pumping: type Sputter Ion
VACUUM PUMPING: Distributed pumping: type <u>Sputter Ion</u> total speed <u>1200 1/s</u> Lumped pumping: type <u>Sputter Ion</u> total speed <u>9200 1/s</u>
VACUUM PUMPING: Distributed pumping: type Sputter Ion total speed <u>1200 1/s</u> Lumped pumping: type Sputter Ion total speed <u>9200 1/s</u> Distance between lumped pumps (m) 3 arg arg in 2.2
VACUUM PUMPING: Distributed pumping: type Sputter Ion total speed ~ 1200 1/s Lumped pumping: type Sputter Ion total speed 9200 1/s Distance between lumped pumps (m) 3 arg @vg. ? How is vacuum pressure monitored? Ion gages (1 at each guadrant)
VACUUM PUMPING: Distributed pumping: type Sputter Ion total speed ~ 1200 1/s Lumped pumping: type Sputter Ion total speed 9200 1/s Distance between lumped pumps (m) 3 arg Mg. ? How is vacuum pressure monitored? Ion gages (1 at each quadrant) discharge-current of lumped Ion Sputter pumps
VACUUM PUMPING: Distributed pumping: type
VACUUM PUMPING: Distributed pumping: type Sputter Ion total speed ~ 1200 1/s Lumped pumping: type Sputter Ion total speed 9200 1/s Distance between lumped pumps (m) 3 arg evg. ? How is vacuum pressure monitored? Ion gages (1 at each quadrant) discharge-current of lumped Ion Sputter pumps Procedures to avoid ion-trapping? No
VACUUM PUMPING: Distributed pumping: type
VACUUM PUMPING: Distributed pumping: type Sputter Ion total speed
VACUUM PUMPING: Distributed pumping: type Sputter Ion total speed 9200 1/s Distance between lumped pumps (m) 3 arg @vg ? How is vacuum pressure monitored? Ion gages (1 at each quadrant) discharge-current of lumped Ion Sputter pumps Procedures to avoid ion-trapping? No Published articles describing the machine and/or vacuum system 1) Proc. 1979 Part. Mce Conf., IEEE Trans act. Nucl.Sc., Vol-NS26, No.3, Jung
VACUUM PUMPING: Distributed pumping: type
VACUUM PUMPING: Distributed pumping: type total speed <u>1200 1/s</u> Lumped pumping: type total speed <u>9200 1/s</u> Distance between lumped pumps (m) 3 arg @vg ? How is vacuum pressure monitored? Ion gages (1 at each quadrant) discharge-current of lumped Ion Sputter pumps Procedures to avoid ion-trapping? No Published articles describing the machine and/or vacuum system
VACUUM PUMPING: Distributed pumping: type total speed ~ 1200 1/s Lumped pumping: type speed 9200 1/s Distance between lumped pumps (m) 3 arg &vrg. ? How is vacuum pressure monitored? Ion gages (1 at each quadrant) discharge-current of lumped Ion Sputter pumps Procedures to avoid ion-trapping? No Published articles describing the machine and/or vacuum system 1) Proc. 1979 Part. Mce Conf., IEEE Trans act. Nucl.Sc., Vol-NS26, No.3, Jung 2) Nucl. Instr. Meth., Vol. 172, Xlos 1,2 May 1980, p.55 3) Proc. 1983 Part. Mce. Conf., Santa Fé Additional features or comments
VACUUM PUMPING: Distributed pumping: type
VACUUM PUMPING: Distributed pumping: type

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and Beam Current (mA) _ Fraction of beam remaining _ Pressure required to achieve c	500 Iesired Ti	1/2 fetime (Tor	r) <u>1.10-</u> °		······
OPERATING EXPERIENCE 1. After first week of beam	Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr) * ¹	Pressure With Beam (Torr) * ¹	Beam Lifetime (Hours)
2. After 2 months of beam					
3. After 1 year of beam			1		
4. NOW	• 2	150	2	1002010	
Comments ^{*1} Pressure meas dipole-chambers roughl	ured in y 25	straight s	sections;	pressure	in
Comments <u>*1</u> Pressure meas dipole-chambers roughl After opening chamber to insta	ured in y 25	straight s times woo ring vacuum	sections; rse component:	pressure	in
Comments <u>*1</u> Pressure meas dipole-chambers roughl After opening chamber to insta 1. After one week	ured in y 25 all a new .2	straight s times woo ring vacuum 4	component:	pressure	in
Comments <u>*1 Pressure meas</u> <u>dipole-chambers rough1</u> After opening chamber to insta 1. After one week 2. After one month	ured in y 25 all a new .2 .2	straight s times woo ring vacuum 4 16	component: 12.10 ⁻⁹ 26.10 ⁻¹	pressure	in
Comments <u>*1 Pressure meas</u> dipole-chambers roughl After opening chamber to insta 1. After one week 2. After one month 3. After 6 months	ured in y 25	straight s times woo ring vacuum 4 16 "	component: 12.10 ⁻⁹ 26.10 ⁻¹	pressure 36.10 ⁻² 12.10 ⁻⁹	in 1.5 3

D-7

ELECTRON STORAGE RING/VACUUM DATA SHEET

Name of the RingADONEDateJuly 1983InstitutionINFNData supplied by S.Tazzari-V.Chimenti
Date of first circulating beam (or goal) <u>December 1967</u>
Beam energy, Typical (E ₀ , GeV) <u>1.5</u>
Avg. Beam current, Typical(I ₀ , mA) 50+80
Max. (I_m, mA) 2×100 Radius of curvature in bend magnets (m)5Ring circumference (m)105
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) <u>9x2 at E_m, I_m</u> or acceleration voltage/turn due to bend magnets at E_0 (kV)
VACUUM CHAMBER:
Aperture:horizontal (m)240vertical(m)80Chamber materialStainless Steel AISI 304LMaterial impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber materialnot different
Chamber preparation before installation <u>Electrolytic treatment in warm alkaline</u>
solutions
In-situ chamber treatment (e.g. bake, glow):bake at 300°C
VACUUM PUMPING:
Distributed pumping: type
Lumped pumping: type Sputter ion total speed 14.000 l/s
Distance between lumped pumps (m) 4.5
How is vacuum pressure monitored? B.A. gages
Procedures to avoid ion-trapping?
Published articles describing the machine and/or vacuum system
_ 1EEE-NS-16, <u>3</u> p. 1073 (1969)
<u>Proceedings of the Vth International Conference on High Energy</u> Accelerators, Frascati, 378 (1965)
Additional features or comments
· · · · · · · · · · · · · · · · · · ·

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ELECTRON STORAGE RING/VACUUM DATA SHEET

DESIRED VACUUM:

Desired beam lifetime (hours)	10
at Beam Energy (GeV)	1.5
and Beam Current (mA)	2x100
Fraction of beam remaining	1/e
Pressure required to achieve	desired lifetime (Torr) <u>1-10-9</u>

OPERATING EXPERIENCE

1.		Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr) Δp/i =	Pressure With Beam (Torr) 3-10 ⁻¹⁰ To	Beam Lifetime* (Hours) rr∕mA
2.]]};];];];];];];];];];];];];];];];];];];		.055		1.7 10 ⁻¹⁰	
3.	###\$\ %###\${!!/?\$J] /}\$J#\$?#\$\$!!//K5/?\$[]/K6/?\$]		.125		$1.2 10^{-10}$	
4.	Mesone /		.176			

Comments	Above values referred to first operation. Ou	r best values of $\Delta p/i$: 1+5.10 ⁻¹¹ Torn
	after about 100 A_h	$(AP = 4 \times 10^{-11} (200) = 8 \times 10^{-9} \text{Torr})$

(100	Ah	=	500	hours	١
.2	A			<u>.</u>)

After opening chamber to install a new ring vacuum component: * see comments

1.	After one week			
2.	After one month			
3.	After 6 months		:	

What procedure is followed when chamber is opened opening to dry air

Comments * not significantly different from above if whole chamber is let up to air

*Fraction of beam remaining is 1/e

ELECTRON STORAGE RING/VACUUM DATA SHEET

\mathcal{D} = \mathcal{D} = \mathcal{D} = \mathcal{D} = \mathcal{D} = \mathcal{D} = \mathcal{D}
Name of the Ring Pholon Factory Date July 20. 1783 Institution National Lak. for High Energy Phys. Data supplied by Masanoni Kolayashi
Date of first circulating deam (or goal) Feb. 27, 182 (4-turn), Harch 11, 182 (accumulated)
Beam energy, Typical (E ₀ , GeV) 2.5 Max. (E _m , Gev) 3.0
Avg. Beam current, Typical (I_0, mA) 150 Max. (I_m, mA) 253
Radius of curvature in bend magnets (m) <u>8.66</u> Ring circumference (m) <u>18 T</u>
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) <u>63.6 witt/mrad</u> or acceleration voltage/turn due to bend magnets at $E_0(kV)$ <u>400 km</u>
VACUUM CHAMBER:
Aperture: horizontal (cm) $140(B)$, $153(Q)$ vertical(cm) $53(B)$ $70(Q)$ Chamber material A-6063 T6, $(\sim 80\%)$ & 505304 , 3041 & 3161 for fullows (~20%) Material impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber material Cu (OFHC)
Chamber preparation before installation <u>No. i.e.</u> as recieved from
factory
In-situ chamber treatment (e.g. bake, glow): baking at 150 a170°C for Al
252 ~ 200°C har SUS in A8 line ArGDC (105% Da) Line President in Prebin
2307 SOD C TOV SOS DIE 40 MS. INCLUSE. (1070 DET former portentie
VACUUM PUMPING:
Distributed pumping: type digde (Ti) has Bending T.S. Phas Q-dust
total speed $15p_1/2 e^{1/2} $
Lumped pumping: type
total speed nominada 120 Us x 50 set
Distance between lumped pumps (m) 1877 m / 50 set
How is vacuum pressure monitored? At first, Inverted Magnetin Gauge &
Now mude - BA - gauge SD set
Procedures to avoid ion-trapping? Electrodes for BrGDC in B-ducts are used
at -400 V. It looks fairly useful but not enough.
Published articles describing the machine and/or vacuum system
Huch Instr. Hethods 177 (1980) 111
Results & experience will be submitted in "Shinker" (in Tapanese) and
JUST.
Additional features or comments
Phiton Factory - page 2

DESTRED VALUUM:					
Desired beam lifetime (hours) at Beam Energy (GeV) and Beam Current (mA) Fraction of beam remaining Pressure required to achieve of	destred 11	$\frac{2.5}{400 \times 500}$	•) ~		
OPERATING EXPERIENCE		••••	·		<u> </u>
 After first week of beam 	Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr) Average Jong the my	Beam Lifetime≭ (Hours)
2. After 2 months of beam			•		
3. After 1 year of beam	<u> </u>	~ 80	1×10">	1~2×109	
4. Now	<u> </u>	~ 85	1×10">	\$1×10-9	450
	- <u></u>		4 <u></u>	· ·	at 100 mA
Comments <u>ArGDC</u> is used	ful for .	reduction	of pressi	ne in for	w curren?
After supply of gas my is reduced by ArGDC,	sleules Self dea	from non- ning is u	inadiate. sefut.	d parts c	the dur
After opening chamber to inst	all a new	ring vacuum	component:		
1. After one week		1	1	1	l

1.	After one week		 	
2.	After one month			
3.	After 6 months		·	

What procedure is followed when chamber	is opened	Baking.	
When new component is installed.	local ArGDC	ville be necessary.	
Comments		0	

Ye *Fraction of beam remaining is _____

Name of the Ring SOR Date 1983-7-19
Institution <u>ISSP</u> , <u>University of Tokyp</u> Data supplied by <u>A. Mikumi and Y. Miyahara</u> Date of first circulating beam (or goal) <u>1979</u> <u>December</u>
Beam energy, Typical (E ₀ , GeV) 0.38
Avg. Beam current, Typical(I_0 , mA) 300
Max. (l_m, mA) 5/0 Radius of curvature in bend magnets (m) /_/ Ring circumference (m) /7.4
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) 0.50 or acceleration voltage/turn due to bend magnets at $E_0(kV)$ 1.68
VACUUM CHAMBER:
Aperture: horizontal (cm) 9 vertical(cm) 3.5 Chamber material SUS 304 304 Material impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber material
Chamber preparation before installation
1 Super-sonic washing in soap and then otheton solution
2 Washing in nitric acid and alcohl
In-situ chamber treatment (e.g. bake, glow): Ar glow discharge in Ar and Or ges Baking at 250°E for 48 hours
VACUUM PUMPING:
Distributed pumping: type noble ion pump,
total speed 1200 Rec
Lumped pumping: type <u>spatter ion pump</u> and Ii getter pump total speed <u>8200 l/sec</u>
Distance between lumped pumps (m) <u>43</u>
How is vacuum pressure monitored? <u>nude ion gauge</u>
Procedures to avoid ion-trapping?
Published articles describing the machine and/or vacuum system T. Miyahara etal, Particle Accel. 7 163(1976) H. Vit
$\frac{11}{10} \frac{11}{10} 11$
Additional features or comments

SOR - page 2

ELECTRON STORAGE RING/VACUUM DATA SHEET

DESIRED VACUUM:

Desired beam lifetime (hours))	<u> </u>			
and Ream Current (mA)	0.3	<u> </u>			<u></u>
Fraction of beam remaining	3/7	<u>v </u>		<u></u>	w
Pressure required to achieve	desired li	fetime (Torr) 10	9	
OPERATING EXPERIENCE					
·	Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr)	Beam Lifetime [,] (Hours)
1. After first week of beam					
2. After 2 months of beam					
3. After 1 year of beam					1
	1300		150	1129	80.4
After opening chamber to ins	tall a new	ring vacuum I	component:	1	I
2. After one month					+
2. After one month			+	<u> </u>	+
3. After 6 months	<u></u>		1	1	<u> </u>
What procedure is followed w	hen chambei	r is opened			
_ opened with d	ry N2 g	zas fille	d and	losed	<u>(</u>
Comments	<u> </u>	<u> </u>			
		·····			.
· •			····		
*Fraction of beam remaining	is				

Name of the RingTRISTAN ACCUMULATION RING KEKDateJuly 23, 1983InstitutionKEKData supplied by G. HorikoshiDate of first circulating beam (or goal)
Beam energy, Typical (E_0 , GeV) 6 Max. (E_m , Gev) 30 Avg. Beam current, Typical(I_0 , mA) 30 Max. (I_m , mA) 30 Radius of curvature in bend magnets (m) 23.2 Ring circumference (m) 377
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) 147 or acceleration voltage/turn due to bend magnets at $E_0(kV)$
VACUUM CHAMBER: Aperture: horizontal (cm) 9.0 vertical(cm) 4.8 Chamber material Aluminum Alloy 6063-T6 Material impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber material
Chamber preparation before installation Special extrusion with oxygen and argon
gas inside the tube.
In-situ chamber treatment (e.g. bake, glow):
VACUUM PUMPING:
Distributed punping: type Sputter Ion Pump
$50 \ 1/s \times 5 \times 56 = 14000 \ 1/s$
Lumped pumping: typeSputter Ion Pumptotal speed $30 \ l/s \times 80 = 2400 \ l/s$
Lumped pumping: type Sputter Ion Pump total speed 30 l/s × 80 = 2400 l/s Distance between lumped pumps (m) 4.4 How is vacuum pressure monitored?Measurement of discharge current of SIP
Lumped pumping: type Sputter Ion Pump total speed 30 l/s × 80 = 2400 l/s Distance between lumped pumps (m) 4.4 How is vacuum pressure monitored?Measurement of discharge current of SIP Procedures to avoid ion-trapping?
Lumped pumping: type total speed Sputter Ion Pump 30 l/s × 80 = 2400 l/s Distance between lumped pumps (m) 4.4 How is vacuum pressure monitored?Measurement of discharge current of SIP Procedures to avoid ion-trapping? Published articles describing the machine and/or vacuum system H. Ishimaru et al., IEEE Trans. NS-30, No.3, 1983
Lumped pumping: type total speed Sputter Ion Pump 30 l/s × 80 = 2400 l/s Distance between lumped pumps (m) 4.4 How is vacuum pressure monitored Measurement of discharge current of SIP Procedures to avoid ion-trapping? Published articles describing the machine and/or vacuum system H. Ishimaru et al., IEEE Trans. NS-30, No.3, 1983

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Name of the RingTRISTAN MAIN RINGDateDateJuly 23, 1983InstitutionData supplied by <u>G. Horikosh</u> Date of first circulating beam (or goal)
Beam energy, Typical (E ₀ , GeV) 30 Max. (E _m , Gev) Avg. Beam current, Typical (I ₀ , mA) 15 Max. (I _m , mA)
Radius of curvature in bend magnets (m) 246.5 Ring circumference (m) 3018
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) <u>4350</u> or acceleration voltage/turn due to bend magnets at $E_0(kV)$
VACUUM CHAMBER:
Aperture: horizontal (cm) <u>11.0</u> vertical(cm) <u>5.4</u> Chamber material Material impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber material
Chamber preparation before installation
Special extrusion(cf. TRISTAN ACCUMULATION RING).
In-situ chamber treatment (e.g. bake, glow):
VACUUM PUMPING:
Distributed pumping: type Sputter Ion Pump total speed 100 $\ell/s/m \times 6m \times 292 = 175,200 \ell/s$
Lumped pumping: type Sputter Ion Pump total speed 30 l/s × 350 = 10,500 l/s
Distance between lumped pumps (m) 8
How is vacuum pressure monitored? <u>Measurement of discharge current of SIP</u>
Procedures to avoid ion-trapping?
Published articles describing the machine and/or vacuum system
Additional features or comments
·
Additional features or comments

Name of the Ring UVSOR Date 15, July, 1983
Institution Inst. for Molecular Science Data supplied by Maketo WATANABE
Date of first circulating beam (or goal) <u>1</u> , November, 1983
Beam energy, Typical (E ₀ , GeV) 0.6
Max. (E _m , Gev) 0.8
Avg. Beam current, Typical(I ₀ , mA) <u>200</u>
Max. (I _m , mA) <u>500</u>
Ring circumference (m) $\leq 3, 6$
$C_{\text{restructure}} = \frac{1}{2} \frac{3}{2} \frac{3}{2} \frac{1}{2} \frac{1}{2}$
Synchrotron radiation power due to bend magnets at E_0 , I_0 (KW) $f_0 U f_1$
VACUUM CHAMBER:
Aperture: horizontal (cm) $1/1$ vertical(cm) 3.8
Chamber material Stainless steel
Material impinged by synchrotron radiation from the bend magnets (photon
absorber) if different from chamber material
Chamber preparation before installation
In-situ chamber treatment (e.g. bake, glow): <u>baking 200°C</u> , argun
discharge (bending section only)
VACUUM PUMPING:
Distributed pumping: type in sputter pump
total speed 1000 l/s
Lumped pumping: type im souther our b
total speed (6000 k/s and themium sublimation pump
Distance between lumped pumps (m) 4 (and reader)
How is vacuum pressure monitored?
now is vacuum pressure montioned: <u>Lon gauge</u> <u>Total 200001/5</u>
Procedures to avoid ion-transing? At near t N's Hunger
Tot present to to to to the topping:
Clearing électroiles can be instatled. y nécessary.
Published articles describing the machine and/or vacuum system
M. Watanabe et al. IEEE Trans. NS-28 (1981), 3175.
"DESIGN OF LIVSTR LIGHT SOURSE AT IMS"
Additional features on commonts
and the second secon

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DESTRED VACUUM	I JI UNAL	ring theoun i たしよ		to vacuu	1 m
UESTRED VALUUM:	ç	le tel	the pull	M (I -	
Desired beam lifetime (hours)	ہے 	4 (louscher	lofetime (S I herry
and Beam Current (mA)	(-00 			
Fraction of beam remaining Pressure required to achieve	desired li	fetime (Torr)/x	10-9	
DPERATING EXPERIENCE					
	Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr)	Beam Lifetime (Hours)
l. After first week of beam					
2. After 2 months of beam					
3. After 1 year of beam					
1. Now				L	
Comments					
Comments					
Comments After opening chamber to inst	all a new	ring vacuum	component:		
Comments After opening chamber to inst L. After one week	all a new	ring vacuum	component:		
Comments After opening chamber to inst L. After one week 2. After one month	all a new	ring vacuum	component:		
Comments After opening chamber to inst L. After one week 2. After one month 3. After 6 months	all a new	ring vacuum	component:		
Comments After opening chamber to inst 1. After one week 2. After one month 3. After 6 months What procedure is followed wh	all a new	ring vacuum	component:		
Comments After opening chamber to inst 1. After one week 2. After one month 3. After 6 months What procedure is followed wh Comments	all a new	ring vacuum	component:		
Comments After opening chamber to inst 1. After one week 2. After one month 3. After 6 months What procedure is followed wh Comments	all a new	ring vacuum	component:		

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Institution Electrotechnical Lab. Date Aug. 6, 83 Data supplied by Takio Tomimasu
Date of first circulating beam (or goal) Oct. 7, '81
Beam energy, Typical (E ₀ , GeV) 0.6 Max. (E _m , Gev) 0.8 (goal) Avg. Beam current, Typical(I ₀ , mA) 90 Max. (I _m , mA) 300 (goal)
Radius of curvature in bend magnets (m) 2.0 Ring circumference (m) 31.44
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) 1.3 kW or acceleration voltage/turn due to bend magnets at $E_0(kV)$ 5.7
VACUUM CHAMBER:
Aperture: horizontal (cm) ± 5.6 vertical(cm) ± 1.8 Chamber material <u>SUS 316L</u> Material impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber material
Chamber preparation before installation
In-situ chamber treatment (e.g. bake, glow): <u>bake and glow-discharge</u>
VACUUM PUMPING:
VACUUM PUMPING: Distributed pumping: type <u>Sputter Ion</u> total speed <u>1500 1/s</u>
VACUUM PUMPING: Distributed pumping: type Sputter Ion total speed 1500 1/s Lumped pumping: type Sputter Ion and Ti-sub total speed 11500 1/s
VACUUM PUMPING: Distributed pumping: type <u>Sputter Ion</u> total speed <u>1500 1/s</u> Lumped pumping: type <u>Sputter Ion and Ti-sub</u> total speed <u>11500 1/s</u> Distance between lumped pumps (m) <u>4.0</u>
VACUUM PUMPING: Distributed pumping: type Sputter Ion total speed 1500 1/s Lumped pumping: type Sputter Ion and Ti-sub total speed 11500 1/s Distance between lumped pumps (m) 4.0 How is vacuum pressure monitored? Ion gauges
VACUUM PUMPING: Distributed pumping: type
VACUUM PUMPING: Distributed pumping: type Sputter Ion total speed
VACUUM PUMPING: Distributed pumping: type Sputter Ion total speed 1500 1/s Lumped pumping: type Sputter Ion and Ti-sub total speed 11500 1/s Distance between lumped pumps (m) 4.0 How is vacuum pressure monitored? Ion gauges Procedures to avoid ion-trapping?
VACUUM PUMPING: Distributed pumping: type total speed 1500 1/s Lumped pumping: type total speed 11500 1/s Distance between lumped pumps (m) 4.0 How is vacuum pressure monitored? Ion gauges Procedures to avoid ion-trapping?
VACUUM PUMPING: Distributed pumping: type Sputter Ion total speed 1500 1/s Lumped pumping: type Sputter Ion and Ti-sub total speed 11500 1/s Distance between lumped pumps (m) 4.0 How is vacuum pressure monitored? Ion gauges Procedures to avoid ion-trapping?
VACUUM PUMPING: Distributed pumping: type total speed 1500 1/s Lumped pumping: type total speed 11500 1/s Distance between lumped pumps (m) 4.0 How is vacuum pressure monitored? Ion gauges Procedures to avoid ion-trapping? Published articles describing the machine and/or vacuum system " A 600-MeV ETL Electron Storage Ring Particle Accelerator Conference Santa Fe, New Mexico March 21-23, 1983 Aduitional features or comments * TERAS, Tsukuba Electron Ring for Accelerating and Storage



DESIRED VACUUM:					
Desired beam lifetime (hours) at Beam Energy (GeV) and Beam Current (mA) Fraction of beam remaining Pressure required to achieve d	esired li	ifetime (Torr)		
OPERATING EXPERIENCE					
	Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr)	Beam Lifetime≭ (Hours)
1. After first week of beam	0.003		3×10^{-10}	7×10^{-9}	1.0
2. After 2 months of beam					
3. After 1 year of beam	0.1		3×10^{-10}	8×10^{-9}	4.0
4. Now					
After opening chamber to insta	all a new	ring vacuum	component:		
1. After one week	0.01	I	5×10^{-10}	6.5×10^{-10}	9 0.5
2. After one month	0.03				0.5
3. After 6 months					
What procedure is followed when CommentsADDRESS: Electron 1-1-	en chamber trotechni 4, Umezon	is opened cal Laborato	Dry N ₂ is ry ra, Nihari-	filled. Gun	
lbar	aki, JAPA	\N	······································	· · · · · · · · · · · · · · · · · · ·	
······································					

*Fraction of beam remaining is <u>1/e</u>

Name of the Ring LEP	Date 21.57 JULY 1983
Institution CEIZN	Data supplied by A.G. MATHEWSON
Date of first circulating beam (or goal)	
Beam energy, lypical (E_0 , Gev) $\pm AGECT(SAI)$ Max. (E_m , Gev) $P_{1+ASC} = 2 - 5$	20 GOV, PHASE 1 - 51 GOV
Avg. Beam current, Typical(Io, mA)	
Max. (I_m, mA) 2 × Radius of curvature in bend magnets (m) 3	$\frac{3 \text{ mA}}{1 \times 10^3}$
Ring circumference (m) 26.659×103	
Synchrotron radiation power due to bend mag or acceleration voltage/turn due to bend	magnets at E_0 , I_0 (kW) 51640 1.2 MW magnets at $E_0(kV)$ <u>86640</u> 15 MW
VACUUM CHAMBER:	125Gev 89MW
Aperture: horizontal (cm) 13,1 Chamber material <u>Al Extrudiate ISC Al</u> Material impinged by synchrotron radiation absorber) if different from chamber materia	vertical(cm) 7.0 $2M_5S$ 6060 from the bend magnets (photon
Chamber preparation before installation AE	TEO ALL MACHINIC AND THET BOOM
	About Thous the to an the
WELDING PLANNES TOBE IS ETEMED IN	A ANDA DISTRICT SOLAL TRACK BAN
E-LEAFED SOI CLEAFNED SEPTICATELY IN	the work with MAYAF GUOWIN
The situ charbon trastrant (a g haka alaw	FURDOM ZIMIT INTE LOO AT
THESTED CHAMBER LIEZDNEHL (E.G. Dake, gibw)	1341CE 24 hans 135 C
VACUUM PUMPING:	
Distributed pumping: type	CTALODG) NEG.
total speed 103 to 20 l	5" per metre defending on gas load
Lumped pumping: type <u>TON PUMP (TRI</u> total speed	ODE) AIR(5)CHA Pton
Distance between lumped numps (m) 20	
How is vacuum pressure monitored? R A	
now is victor pressure monitored: <u>IS A le</u>	INTERNO ADDAES F TON FORFS
Procedures to avoid ion-trapping? Non	ي ال
Published articles describing the machine a	and/or vacuum system
LEPMACHINE - LEP STUDY GROUP C	67KN/ISA-66P/79-33 1979
VALUCH SYSTEM - THE LEP VALUUM	SUSTEM LEPNOTE 449 7th
JUNE 1983 PRESENTED AT 9th Int V	FI CONG. MAPRID SUPT- 1983
Additional features or comments Duc TO	THE SIZE OF THE MUTCHINE
ONLY 3 SOCALLED PILOT SETTORS	WILL BE FULLY INSTRUMENTED
(~ 1422 m = 3+471 m) with	VACUUM GAUGES AND RESIDUAL
GAS AUGLYZER PERMANENTLY C	ONNUCTED TO THE CENTRAL
COMPUTER SYSTEM. ALSO ALL CH	AMBARS WILL BE COATED WITH
The All Court Dial	

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ELECTRON STORAGE RING/VACUUM DATA SHEET

-	· · · · · · · · · · · ·	001	1	· · /		
Des	ired beam lifetime (hours)	204	due lo	bean f	zas	
	and Beam Current (mA)	2×3~4	at 51 Gev	less at	Ingher en	naries
Fi	action of beam remaining	decined 14		· · · · · · · · · · · · · · · · · · ·	-9	
rre:	sure required to achieve (UESTRED IT	iretame (jorn	1 _ 2000	10	
OPER	ATING EXPERIENCE					
		Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Be <i>a</i> m (Torr)	Pressure With Beam (Torr)	Beam Lifetime (Hours)
1.	After first week of beam	<u></u>				
2.	After 2 months of beam					
3.	After 1 year of beam					
4.	Now					<u> </u>
Aft	er opening chamber to inst	all a new	ring vacuum	component:		
 Aft 1.	er opening chamber to inst After one week	all a new	ring vacuum	component:		
Aft 1. 2.	er opening chamber to inst After one week After one month	all a new	ring vacuum	component:		
Aft 1. 2. 3.	er opening chamber to inst After one week After one month After 6 months	all a new	ring vacuum	component:		
Aft 1. 2. 3.	er opening chamber to inst After one week After one month After 6 months t procedure is followed wh	all a new	ring vacuum	component:		
Aft 1. 2. 3. Wha	er opening chamber to inst After one week After one month After 6 months t procedure is followed wh	all a new	ring vacuum	component:		
Aft 1. 2. 3. What Com	er opening chamber to inst After one week After one month After 6 months It procedure is followed wh	all a new	ring vacuum	component:		
Aft 1. 2. 3. What Com	er opening chamber to inst After one week After one month After 6 months It procedure is followed wh	all a new	ring vacuum	component:		
Aft 1. 2. 3. What Com	er opening chamber to inst After one week After one month After 6 months t procedure is followed wh ments	all a new	ring vacuum	component:		

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Name of the Ring <u>SRS</u> Date <u>15-7-83</u> Institution <u>DARESBULY</u> <u>LABUSATOR</u> Data supplied by <u>G.SAXON</u> Date of first circulating beam (or goal)
Beam energy, Typical (E ₀ , GeV) $2 \cdot 0$ Max. (E _m , Gev) $2 \cdot 0$ Avg. Beam current, Typical(I ₀ , mA) 250 Max. (I _m , mA) 370 Radius of curvature in bend magnets (m) $5 \cdot 56$ Ring circumference (m) 20
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) 70 or acceleration voltage/turn due to bend magnets at $E_0(kV)$ 255
VACUUM CHAMBER:
Aperture: horizontal (cm) 16 to 11.5 vertical(cm) 2.7 to 4.5 Chamber material Stain less Steel Material impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber material <u>Copper</u>
Chamber preparation before installation) Degrecie
ii) Glow Discharge
iii) Bake-out to 300°C (where practicable not r.f. cavities)
In-situ chamber treatment (e.g. bake, glow): <u>Bake out 200°</u> (except r. 1. savites)
VACUUM PUMPING:
Distributed pumping: type <u>Diode ion pump</u> total speed <u>~ 3200 1/s ~ + 10⁻⁹ torr</u>
Lumped pumping: type <u>Torode ion journet + Sublimation Pump</u> total speed <u>~ 32001/s</u> ~ 70001/s (at10-4 tort)
Distance between lumped pumps (m) <u>6</u>
How is vacuum pressure monitored? <u>B.A. Ion Sanges</u> <u>Straights</u>
Procedures to avoid ion-trapping? Clearing electoudes mstalled but not
used because ion effects are not ingeneral destanctive
Published articles describing the machine and/or vacuum system
828 Vacuum System Vacuum 28-471(1978)
See also Design Study for a Deducated Source of Synchrotron
Radiation, D.L. Report DL/SRF/R2 (1975)
Additional features or comments

SRS · page 2

ELECTRON STORAGE RING/VACUUM DATA SHEET

DESIRED VACUUM:

Desired beam lifetime (hours)	10				
at Beam Energy (GeV)	2				
and Beam Current (mA)	370				
Fraction of beam remaining	1/2				
Pressure required to achieve	desired	ifetime	(Torr)	10-9 1005	

ressure requires to conteve destred interme (1011)

OPERATING EXPERIENCE

		Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr)	Beam Lifetime* (Hours)
1.	After first week of beam					
2.	After 2 months of beam					
3.	After 1 year of beam	÷				
4.	Now					

Comments June 80 - Nov. 80 Unbaked Integr. Dose < 1Ah 11fe ~ 30min 100m A Sept-81 Baked 1.8 SeV 1. D 30 Ah de 10"-10" FurrImA life 8-10h (see attached curve for fur thes details on intensity dependence) Sept-82 Baked 2.0 SeV 1. D: 200Ah de 10"-10" Forr/mA life ~202 (Several sectors had been up to atmaphere in this time)

After opening chamber to install a new ring vacuum component:

- 1. After one week
- 2. After one month
- 3. After 6 months

	·		

Boke out to 200° What procedure is followed when chamber is opened (except carities which are rit conditioned comments. There have been a series of vacuum accidents wondows etc) in 1983. and a few small leaks which must statistics. -ifetime is ~ 10h at 100m of now inthe Average Pressure Strught Sections 1-2 ×109 torr)

*Fraction of beam remaining is <u>//e</u>_____



ELECTRON STORAGE RING	VACUUM DATA SHEET
Name of the Ring <u>SURF</u> Institution <u>NBS</u> Date of first circulating beam (or goal)	Date 23 July, 1987 Data supplied by <u>LR Hughey</u> 1973 on 1974
Beam energy, Typical (E_0 , GeV) Max. (E_m , GeV) Avg. Beam current, Typical (I_0 , mA) Max. (I_m , mA)	2 0 (or a little more) 15 same
Radius of curvature in bend magnets (m) Ring circumference (m)	0.84 2.216
Synchrotron radiation power due to bend mag or acceleration voltage/turn due to bend	nets at E _O , I _O (kW) magnets at E _O (kV)
VACUUM CHAMBER:	
Aperture: horizontal (cm) 25 Chamber material 309 Stanker Material impinged by synchrotron radiation absorber) if different from chamber materia	vertical(cm) /0 stel from the bend magnets (photon il
Chamber preparation before installation	baked at ~250°C
In-situ chamber treatment (e.g. bake, glow)	: bake at ~ 130-150 °C.
VACUUM PUMPING:	
Distributed pumping: type <u>internal</u> total speed <u>halding</u> pu	on pump elements and one 200 l/s mp total speed ~ 100 l/s
Lumped pumping: type	•
Distance between lumped pumps (m)	
How is vacuum pressure monitored? <u>a</u> <u>su</u>	igle 10n gas
Procedures to avoid ion-trapping?	1010
Published articles describing the machine a	and/or vacuum system
for any additional informat	ion contact:
Lanny Hughey	
NBS, Physic A 251,	Washington, DC 20234
Additional features or comments	

SURF - Fage 2

ELECTRON STORAGE RING/VACUUM DATA SHEET

DESIRED VACUUM:

Desired beam lifetime (hours)	let ~ 10 × 10-9 the vocum seems	
at Beam Energy (GeV)	to impose a 1/2 life of about 6 hrs.	
and Beam Current (mA)	let our usual beam ourrents of 10-30 m	A
Fraction of beam remaining	our life time is Jouschak limited.	
Pressure required to achieve	desired lifetime (Torr)	

OPERATING EXPERIENCE

		Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr)	Beam Lifetime* (Hours)
1.	After first week of beam					
2.	After 2 months of beam					
3.	After 1 year of beam			·		
4.	Now			ĺ		

We have never observed Comments to store our even 35-45 mA eams.

After opening chamber to install a new ring vacuum component:

1.	After one week		 •		
2.	After one month	-			
3,	After 6 months	. –			· .

What procedure is followed when chamber is opened The chamber vented on Friday and new features ten pamped out Comments 🛛 🎢 ano me the maure - Alexday morn near no inici èce. usal 6-10×10-9.

*Fraction of beam remaining is _

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Name of the Ring $SPEAR$ Date $7/19/83$
Institution SLAC Data Supplied By B. Scott
Page of this chical (E. GeV) $15 - 35$
Hax. $(E_m, Gev) = \frac{3.7}{3.7}$
Avg. Beam current, Typical(I ₀ , mA) 100 mA at 3 Gev
Radius of curvature in bend magnets (m) 12.716 Ring circumference (m)ARC + IR 234.1 ARCS 189.2
Synchrotron radiation power due to bend magnets at E_0 , E_0 (kW) 56.4 KW/Beam at 3 GeV or acceleration voltage/turn due to bend magnets at $E_1(kV)$ 100 mA
VACUUM CHAMBER:
Aperture: horizontal (cm) 15.54 vertical(cm) 4.62 Chamber material Aluminum 6061-T 6 Material impinged by synchrotron radiation from the benz magnets (photon absorber) if different from chamber material Aluminum
Chamber preparation before installation
Chemical etch, bakeout to 170°C
In-situ chamber treatment (e.g. bake, glow): <u>None accept after</u> accidental venting when bakeout may be necessary
VACUUM PUNPING:
Distributed pumping: type Sputter Lon (Diode) total speed 36 (600)= 21,600 L/s
Lumped pumping: type Sputter Ion (trinde)
total speed <u>Arcs 16 (400) 6,400 ijters/sec</u>
Unstance between lumped pumps (m)
now is vacuum pressure monitored: <u>BA Ion Gauge</u>
Procedures to avoid ion-trapping?N/A
Published articles describing the machine and/or vanue system
Vacuum system for Stanford Storage Ring, SPEAR, Journal Vac. Sci & Tech vol.8 No.1
Vacuum sysem for Stanford - LBL Storage Ring, PEP, SLAC Pub. 1547, 1975
Additional features or coments

SPEAR - page 2

ELECTRON STORAGE RING/VACUUM DATA SHEET

DESIRED VACUUM:

OPERATING EXPERIENCE		- 			
UPERATING EXTERIENCE	Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr)	Beam Lifetime (Hours)
1. After first week of beam					
2. After 2 months of beam					
3. After 1 year of Dean					
4 • NOW		11	والمتحرب والمستجل المسيح المارا الأرام المتح		<u></u>
Comments <u>Clean-up t</u> on beam ene during the	ime after o rgy, curren start-up pe	pening of sys t and bunch s riod.	ter depends tructure of	beam	
Comments <u>Clean-up t</u> on beam ene during the After opening chamber to ins	ime after o rgy, curren start-up pe stall a new	ring vacuum	tes depends tracture of Component:	beam	
Comments <u>Clean-up t</u> on beam ene during the After opening chamber to ins 1. After one week	ime after o rgy, curren start-up pe stall a new	ring vacuum	tes depends tructure of component:	beam	······································
Comments <u>Clean-up t</u> on beam ene during the After opening chamber to ins 1. After one week 2. After one month	ime_after_o rgy, curren start-up pe stall a new	pening of sys t and bunch s riod. ring vacuum	tes depends tructure of component:	beam	
Comments <u>Clean-up t</u> on beam ene during the After opening chamber to ins 1. After one week 2. After one month 3. After 6 months	ime_after_o rgy, curren start-up pe stall a new	pening of sys t and bunch s riod. ring vacuum	tes depends tructure of component:	beam	
Comments <u>Clean-up t</u> on beam ene during the After opening chamber to ins 1. After one week 2. After one month 3. After 6 months	ime_after_o rgy, curren start-up_pe stall a new	ring vacuum	tes depends tructure of corponent:	beam	
Comments <u>Clean-up t</u> on beam ene during the After opening chamber to ins 1. After one week 2. After one month 3. After 6 months What procedure is followed w and flanges; smoke free at	ime_after_or rgy, curren start-up pe stall a new	ring vacuum r is opened f tunnel roof	tes depends tructure of component: Component:	beam	a
Comments <u>Clean-up t</u> on beam ene during the After opening chamber to ins 1. After one week 2. After one woek 2. After one month 3. After 6 months What procedure is followed w and flanges; smoke free att Comments work area is isolar	<pre>ime_after_or rgy, curren start-up pe stall a new </pre>	ring vacuum r is opened f tunnel roof	tes depends tructure of component: <u>Clean-up o</u> <u>blocks are</u> g to reduce	<u>beam</u> <u>f work are</u> <u>removed th</u> air and du	a st

*Fraction of beam remaining is

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Name of the Ring PEP	Date 7/14/83
Institution Date of first circulating beam (or coal)	Data supplied by J. Jurow
Beam energy. Typical (Fo. GeV) 14.5	4/21/00
Max. (E _m , Gev)	
Avg. Beam current, $Iypical(I_0, mA) = 35$ Max. $(I_m, mA) = 42$	
Radius of curvature in bend magnets (m)	165.5
Synchrotron radiation power due to head ma	$E_{230,3}$
or acceleration voltage/turn due to bend	magnets at $E_0(kV)$
VACUUM CHAMBER:	
Aperture: horizontal (cm) 9	vertical(cm) 5
Material impinged by synchrotron radiation	from the bend magnets (photon
absorber) if different from chamber materi	alAluminum
Chamber preparation before installation	Clean and Bake
	· · · · · · · · · · · · · · · · · · ·
In-situ chamber treatment (e. n. hake). Bake due to accidental let-up
TH-sted chamber of cadicity (c.g. bake, grow	/
VACUUM PUMPING:	
Distributed pumping: type <u>Sputter Ion</u> total speed <u>9600</u> e/sec	
Lumped pumping: typeSputter Ion	
total speed <u>51000 %/sec</u>	
Distance between lumped pumps (m) 14	
How is vacuum pressure monitored? <u>Bayard</u> Computer recorded	-Alpert Gauges
Procedures to avoid ion-trapping? <u>None</u>	· · · · · · · · · · · · · · · · · · ·
Published articles describing the machine Vacuum System for the Stanford-LBC Stor	and/or vacuum system age
Ring (PEP), IEEE Transactions Vol. NS-2	2, No. 3, 1975
Additional features or comments	

PEP page 2

Desired beam lifetime (hours)	4			· ·	, [*]
at Beam Energy (GeV)	14.5	·			
Eraction of beam remaining	<u>35</u>	an 2 hauna			
Pressure required to achieve d	lesirea li	fetime (lorr)		
OPERATING EXPERIENCE		, ,			
		Integrated	Pressure	Pressure	1
	Beam	Bean	Without	With	Beam
	Current	Current	Bean (Tenn)	Bean	Life
· · · · · · · · · · · · · · · · · · ·	(A)	(A-nours)	(iêr r.)		(nou)
1. After first week of beam			· · · · · · · · · · · · · · · · · · ·		
2. After 2 months of beam			·		
3. After 1 year of beam		-			
4. Now					
	· ·			r +u	
Comments					
			•		
After opening chamber to insta	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week 2. After one month	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week 2. After one month 3. After 6 months	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week 2. After one month 3. After 6 months	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week 2. After one month 3. After 6 months	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week 2. After one month 3. After 6 months What procedure is followed what	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week 2. After one month 3. After 6 months What procedure is followed what	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week 2. After one month 3. After 6 months What procedure is followed what Comments	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week 2. After one month 3. After 6 months What procedure is followed what Comments	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week 2. After one month 3. After 6 months What procedure is followed what Comments	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week 2. After one month 3. After 6 months What procedure is followed what Comments	all a new	ring vacuum	component:		
After opening chamber to insta 1. After one week 2. After one month 3. After 6 months What procedure is followed what Comments	all a new	ring vacuum	component:		

Name of the RingSLC-eDamping RingDate7/13/83InstitutionStanford Linear Acc. CenterData supplied byD. WrightDate of first circulating beam (or goal)Feb. 1983
Beam energy, Typical (E0, GeV) 1.21 GeV (950 MeV) Max. (Em, Gev) 1.21 GeV Avg. Beam current, Typical (I0, mA) 141 mA Max. (Im, mA) 141 mA Max. (Im, mA) 141 mA Radius of curvature in bend magnets (m) 2.049 m Ring circumference (m) 35.27
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) 13.1 kW or acceleration voltage/turn due to bend magnets at $E_0(kV)$.
VACUUM CHAMBER:Aperture: horizontal (cm)2.0 cmvertical(cm)1.5 cmChamber material6061 - T6 Aluminum & Stainless SteelMaterial impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber material
Chamber preparation before installation <u>N2</u> purge bakeout @ 180°c followed
<u>by vacuum bakeout @ 180°c</u>
VACUUM PUMPING:
Distributed pumping: type <u>Diode sputter - ion pumps</u> total speed 7.3 x 10 %/s
Lumped pumping: type Diode Sputter - ion pumps total speed 960 %/s
Distance between lumped pumps (m) 1.3 m
How is vacuum pressure monitored? <u>nude B-A ion qaumes</u>
Procedures to avoid ion-trapping? Clearing field electrodes
Published articles describing the machine and/or vacuum system
SLAC Linear Collider Conceptual Design Report (SL&C Report -229)
Additional features or comments

SLC Damp - page 2

ELECTRON STORAGE RING/VACUUM DATA SHEET

DESIRED VACUUM:

Desired beam lifetime (hours) at Beam Energy (GeV) and Beam Current (mA) Fraction of beam remaining Pressure required to achieve a	50 mi <u>1.2] (</u> 141 m/ 1/e Jesired 1	in (see com GeV A ifetime (Torn	nents) r) <u>5 x 10</u>	9	
OPERATING EXPERIENCE	•				
	Beam Current (A) 958 MeV	Integrated Bean Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr)	Beam Lifetime* (Hours)
1. After first week of beam	0.2 mA	22.5 mA-hr	3.5 x 10 ⁻⁹	1.1×10^{-8}	<u>50 min</u>
2. After 2 months of beam	0.5 mA	180mA-hr	5.8×10^{-9}	1.0 x 10 ⁻⁸	<u>.50 min</u>
3. After 1 year of beam	جە جە 				
4. Now	0.9mA	360mA-hr	5.8×10^{-9}	8.8×10^{-9}	50 min
			ی ی ی د د دی ی میرو د در و د میرو ا ۱۹	Gale	
After opening chamber to inst	all a new	ring vacuum	component:	8 o o 10 ⁻	8 E0 min
2. After one month	<u> </u>	22.5 mA-nr	E 0 - 10	$\frac{12.8 \times 10}{10 \times 10^{-10^{-10^{-10^{-10^{-10^{-10^{-10^{-$	S0 min
2. After 6 months	_U.SMA_	90mA-nr	<u>5.6 X 10</u>	1.0 × 10	<u> </u>
S. RICEL O MONCHS		1		<u></u>	L
What procedure is followed wh from liquid); maintain N ₂	en chamben purge whi	r is opened le open; pur	<u>Vent to d</u> rge overnigh	ry N ₂ (boil t after clo	-off sing if poss
Comments					· · · · · · · · · · · · · · · · · · ·
		· · · · · · · · · · · · · · · · · · ·			
				· · ·	
	· .				
			· · ·		
	:	· .	4 . · · ·	· · · ·	· a.
*Fraction of beam remaining i	s1/	e			·• .
	D		t and the second se		

Name of the Ring $N/S/S$ $V(J)/$ Date 7-/3-83
Institution Brookhaven Nat Lab Data supplied by J. Schuchman
Date of first circulating beam (or goal) Aug 1981
Beam energy, Typical (E ₀ , GeV) .75
Avo, Beam current, Typical (Io, mA) 200
Max. (Im, mA)
Radius of curvature in bend magnets (m) <u>1.91</u>
or acceleration voltage/turn due to bend magnets at E ₀ , I ₀ (KW) <u>14</u>
VACUUM CHAMBER:
Aperture: horizontal (cm) & vertical(cm) 4.2
Chamber material Alum. VAW Alloy 19/06 LVW
Material impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber material
Chamber preparation before installation
Caustic Etch, see NSLS SPEC 565-07-12-1-18
In-situ chamber treatment (e.g. bake, olow):
Vacuum Bakant 150°s for 72 hos
Vaccom Darebul 100 C for 12 mil.
VACUUM PUMPING:
Distributed pumping: type Sputter Ion - Diode
total speed 1800 River at 10-9 Torr
Lumped pumping: type Sputter Ion (P4E DI)
total speed 1320 flsec at 10-970rr
Distance between lumped pumps (m) <u>4.3 Avg</u>
How is vacuum pressure monitored? <u>Sputter Ion Pump Current</u>
Presedunes to sucid for transis 2 of 1 /
Procedures to avoid ion-trapping? <u>Chamber has provisions for clearing</u>
Procedures to avoid ion-trapping? <u>Chamber has provisions for clearing</u> <u>cleatrodes; Option of I bunch 3 bunch or 9 bunch with gap operation</u> .
Procedures to avoid ion-trapping? <u>Chamber has provisions for clearing</u> <u>cleatrodes; Option of Ibunch 3 bunch or 9 bunch with gap operation</u> . Published articles describing the machine and/or vacuum system
Procedures to avoid ion-trapping? <u>Chamber has provisions for clearing</u> <u>electrodes; Option of Ibunch 3 bunch or 7 bunch with gap operation</u> . Published articles describing the machine and/or vacuum system <u>Vacuum System for NSLS</u> , J. Vac. Scj. Technol., 16(2), Mar/Apr. 1977.720.
Procedures to avoid ion-trapping? <u>Chamber has provisions for clearing</u> <u>electrodes; Option of Ibunch, 3 bunch or 9 bunch with gap operation</u> . Published articles describing the machine and/or vacuum system <u>Vacuum System for NSLS</u> , J. Vac. Scj. Technol., 16(2), <u>Mar/Apr. 1979</u> 720. <u>Final Design & Status of the NSLS Vacuum System</u> , J. Vac. Scj.
Procedures to avoid ion-trapping? <u>Chamber has provisions for clearing</u> <u>clectrodes; Option of Ibunch 3bunch or 9 bunch with gap operation</u> . Published articles describing the machine and/or vacuum system <u>Vacuum System for NSLS</u> , J. Vac. Scj. Technol., 16(2), HarfApr. 1979.720. <u>Final Design & Status of the NSLS Vacuum System</u> , J. Vac. Sci. <u>Technol. A-1(2)</u> , Apr-June 1983, 196.
Procedures to avoid ion-trapping? <u>Chamber has provisions for clearing</u> <u>clectrodes; Option of Ibunch 3 bunch or 9 bunch with gap operation</u> . Published articles describing the machine and/or vacuum system <u>Vacuus System for NSLS</u> , J. Vac. Scj. Technol., 16(2), MarfApr. 1979 720. <u>Final Design & Status of the NSLS Vacuum System</u> , J. Vac. Scj. <u>Technol. A-1(2), Apr-June 1983</u> , 196. Additional features or comments
Procedures to avoid ion-trapping? <u>Chamber has provisions for clearing</u> <u>electrodes; Option of Ibunch 3 bunch or 9 bunch with gap operation</u> . Published articles describing the machine and/or vacuum system <u>Vacuus System for NSLS</u> , J. Vac. Scj. Technol., 16(2), <u>Mar/Apr. 1979</u> , 720. <u>Final Design & Status of the NSLS Vacuum System</u> , J. Vac. Sci. <u>Technol. A-1(2)</u> , <u>Apr-June 1983</u> , 196. Additional features or comments <u>Ti Sublimination Rumping Speed</u> 7000 <u>R/sec</u>

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ELECTRON	STORAGE I	RING/VACUUM D	ATA SHEET		, , , -,
DESIRED VACUUM:		· · · · · · · · · · · · · · · · · · ·			
Desired beam lifetime (hours) at Beam Energy (GeV) and Beam Current (mA) Fraction of beam remaining Pressure required to achieve of	5 . 73 100 Jesired Ti	hrs 0 fetime (Torr) /0-	9	
OPERATING EXPERIENCE					
	Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr)	Beam Lifetime* (Hours)
1. After first week of beam					•
2. After 2 months of beam					
3. After 1 year of beam					·
4. Now		·			
After opening chamber to insta	all a new	ring vacuum (component:		í.
1. After one week					
2. After one month	<u></u>			<u> </u>	· · · · · · · · · · · · · · · · · · ·
3. After 6 months	·			<u>]</u>	· · · · ·
What procedure is followed when <u>Vent with LN= trapp</u>	en chamber ed dry	is opened			
Comments <u>Future plans</u>	to ven	t with	LN2 6-1	/-•++.	
		· · · · · · · · · · · · · · · · · · ·			
				······	
*Fraction of beam remaining is	s				

NSLS VUV - page 2

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Name of the Ring A/S/S X-RAY Date 7-13-83
Institution Data supplied by J. Schuchman
Date of first circulating beam (or goal) <u>Sept 1982</u>
Beam energy, Typical (E ₀ , GeV)
Avg. Beam current, Typical(I_0 , MA) /D
Max. (I _m , mA) 500
Radius of curvature in bend magnets (m) (2.875) Ring circumference (m) (70)
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) 25/ or acceleration voltage/turn due to bend magnets at $E_0(kV)$ 505
VACUUM CHAMBER:
Aperture: horizontal (cm) 8 vertical(cm) 4.2
Chamber material Alum. VAW Alloy 19/06 LVW
absorber) if different from chamber material
Chamber preparation before installation
Caustic Etch, see NSIS SPEC SLS-07.12-1-18
Vacuum Bakeout 150°c 48 hrs.
In-situ chamber treatment (e.g. bake, glow):
Vacuum Bakeout 150°c for 72 hrs
VACUUM PUMPING:
Distributed pumping: type <u>Spuffer Ion - Diode</u>
Lumpod pumping: tupo =
total speed $2640 \frac{place}{2640} = 10^{-9} Tarr$
Distance between lumped pumps (m) 5.3
How is vacuum pressure monitored? <u>Sputter Ion Pump Current</u>
Presedures to avoid ion transing? d/ / /
Procedures to avoid ion-trapping: <u>Chamber has provision for clearing</u>
OPECIFO des; Oplion of Ibunch, 3 bunch, or 30 bunch with gap operation
Published articles describing the machine and/or vacuum system
Vacuum System for NSLS, J. Vac. Sci. Technol. 16 (2), Mar/Apr. 1979, 720.
Final Design & Status of the NSLS Vacuum System, J. Vac. Sci
1echnol. A-1(2), Apr-June 1983, 196.
Additional features or comments
li Sublimination lumping Speed 16800 \$/soc

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DESIRED VACUUM:					
at Beam Energy (GeV)	2	<u>.5</u>		······································	
and Beam Current (mA)	\$	00			
Pressure required to achieve of	desired 11	fetime (Torr)/0-	9 Torr	
DPERATING EXPERIENCE					an an an Anna An Anna Anna Anna
	Beam Current (A)	Integrated Beam Current (A-hours)	Pressure Without Beam (Torr)	Pressure With Beam (Torr)	Beam Lifetim (Hours)
. After first week of beam					j, i de Sjin
. After 2 months of beam				•	
After 1 year of beam				·** er	
• Now					
_					
omments					• · · · ·
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Name of the Ring <u>Advanced Light Source (ALS)</u> Date <u>7/7/83</u> Institution <u>Lawrence Berkeley Laboratory</u> Data supplied by <u>Kurt Kennedy</u> Date of first circulating beam (or goal) <u>1988</u>
Beam energy, Typical (E_0 , GeV)1.3Max. (E_m , Gev)1.9Avg. Beam current, Typical(I_0 , mA)400Max. (I_m , mA)400Radius of curvature in bend magnets (m)3.97Ring circumference (m)182.
Synchrotron radiation power due to bend magnets at E_0 , I_0 (kW) or acceleration voltage/turn due to bend magnets at $E_0(kV)$ 64
VACUUM CHAMBER: Aperture: horizontal (cm)3.2 vertical(cm)2.5 Chamber material Al Alloy Material impinged by synchrotron radiation from the bend magnets (photon absorber) if different from chamber material
Chamber preparation before installation <u>Perchlorethylene vapor degreasing</u> -
alkaline detergent – demineralized water
In-situ chamber treatment (e.g. bake, glow): <u>glow-discharge</u>
VACUUM PUMPING:
Distributed pumping: type <u>NEG (or cryo, or Ti-sub being studied)</u> total speed <u>40,000 1/s</u>
Distributed pumping: type NEG (or cryo, or Ti-sub being studied) total speed 40,000 1/s Lumped pumping: type Sputter Ion total speed 18,000
Distributed pumping: type NEG (or cryo, or Ti-sub being studied) total speed 40,000 1/s Lumped pumping: type Sputter Ion total speed 18,000 Distance between lumped pumps (m) Avg. 4.0 meter
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Distributed pumping: type NEG (or cryo, or Ti-sub being studied) total speed 40,000 1/s Lumped pumping: type Sputter Ion total speed 18,000 Distance between lumped pumps (m) Avg. 4.0 meter How is vacuum pressure monitored Ion gages Procedures to avoid ion-trapping Critical ion mass > 10 amu except 250 bunch mode. Then 250 full and 54 empty buckets should avoid trapping. Published articles describing the machine and/or vacuum system "The Advanced Light Source" Particle Accelerator Conference Santa Fe, Vew Mexico March 21-23, 1983 Additional features or comments See enclosed. Pumping speed shown above is the speed through the slot connecting storage ring and antechamber.
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Distributed pumping: type NEG (or cryo, or Ti-sub being studied) total speed 40,000 1/s Lumped pumping: type Sputter Ion total speed 18,000 Distance between lumped pumps (m) Avg. 4.0 meter How is vacuum pressure monitored Ion gages Procedures to avoid ion-trapping Critical ion mass > 10 anu except 250 bunch mode. Then 250 full and 54 empty buckets should avoid trapping. Published articles describing the machine and/or vacuum system "The Advanced Light Source" Particle Accelerator Conference Santa Fe, New Mexico March 21-23, 1983 Additional features or comments See enclosed. Pumping speed shown above is the speed through the slot connecting storage ring and antechamber. DESIRED VACUJM: Desired beam lifetime (hours) > 6 hrs. (Touschek + gas scattering) at Beam Energy (GeV) 1.3 and Beam Current (mA) 400
Distributed pumping: type NEG (or cryo, or Ti-sub being studied) total speed 40,000 1/s Lumped pumping: type Sputter Ion total speed 18,000 Distance between lumped pumps (m) Avg. 4.0 meter How is vacuum pressure monitored Ion gages Procedures to avoid ion-trapping Critical ion mass > 10 anu except 250 bunch mode. Then 250 full and 54 empty buckets should avoid trapping. Published articles describing the machine and/or vacuum system "The Advanced Light Source" Particle Accelerator Conference Santa Fe, Vew Mexico Santa Fe, Vew Mexico March 21-23, 1983 Additional features or comments See enclosed. Pumping speed shown above is the speed through the slot connecting storage ring and antechamber. DESIRED VACUJM: Desired beam lifetime (hours) > 6 hrs. (Touschek + gas scattering) at Beam Energy (GeV) 1.3 and Beam Current (mA) 400 Fraction of beam remaining 1/e

OPERATING EXPERIENCE (None)

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DEPARTMENT OF THE NAVY NAVAL WEAPONS CENTER CHINA LAKE, CALIFORNIA 93855

IN REPLY REFER TO: 3813/VR:st Reg: 381-539-83 12 October 1983

R. T. Avery Lawrence Berkeley Laboratory 1 Cyclotron Road Berkeley, California 94720

Dear Bob:

For your report of the Synchrotron-Radiation Vacuum Workshop, I would like to suggest both optimistic and cautionary comments. The question relates to the extrapolation of both experience and the DESY model to much higher photonflux densities relevant to the ALS undulator beam lines. The optimistic comment comes from the prediction by the DESY model of "intensity saturation" of the contamination rate. I have replotted their Eq. 2 on a log-log plot showing four decades of intensity to illustrate the effect. For pressures of 10^{-9} T and below, a hundred-fold increase in intensity produces less than a two-fold increase in contamination rate.

The first cautionary comment relates to the combination of high intensity and high pressure. In this regime, the contamination rate increases linearly with intensity, and a hundred-fold increase in intensity would decrease the mirror lifetime from ~ 3 mo to ~ 0.03 mo, or about one day. Thus, undulator radiation must never strike a mirror surface when the ambient pressure is high.

The second caution is the obvious one of relying on the model far outside its region of verification. Although undulator radiation should not be intense enough to stimulate non-linear multiphoton excitations, there could be increases in the cracking cross section especially in FEL beams. If so, the contamination rate would increase sharply above the threshold intensity. The true saturation would occur when every molecule striking the surface is cracked, and even at 10^{-10} T this would produce of order 10 atomic layers of carbon per day, or a mirror lifetime of 1 - 10 days.

These few additional comments should provide a more reasoned report on these problems, as well as a better basis for the recommendations.

Sincerely,

V. Rehn

Enclosure: (1) Log 10 Graph



Enc1 (1)
This report was done with support from the Department of Energy. Any conclusions or opinions expressed in this report represent solely those of the author(s) and not necessarily those of The Regents of the University of California, the Lawrence Berkeley Laboratory or the Department of Energy.

Reference to a company or product name does not imply approval or recommendation of the product by the University of California or the U.S. Department of Energy to the exclusion of others that may be suitable.

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